

SN8PC20

USER'S MANUAL

Version 0.6

SONIX 8-Bit Micro-Controller

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AMENDENT HISTORY

Version	Date	Description			
VER 0.1	Oct. 2007	First issue.			
VER 0.2	Nov. 2007	Modify 455KHz crystal application circuit.			
		2. Add "@GreenMode" macro to control system green mode.			
		3. Modify IR application circuit.			
VER 0.3	Jan. 2008	1. Add "Development Tool" section.			
		2. Modify internal low RC frequency to 10KHz @3V.			
VER 0.4	May. 2009	1. Modify some formals.			
		2. Add IHRC frequency curves.			
VER 0.5	Jun. 2011	Add external low clock crystal type 32KHz.			
VER 0.6	Sep. 2011	1. Add SN8PC2016S and SN8PC2014S package type.			



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1 PRODUCT OVERVIEW

1.1 FEATURES

♦ Memory configuration OTP ROM size: 2K * 16 bits. RAM size: 56 * 8 bits.

♦ 4 levels stack buffer.

♦ I/O pin configuration

Bi-directional: P0, P1, P5. 400mA IR output pin: P5.4/IROUT Wakeup: P0, P1 level change trigger. Pull-up resisters: P0, P1, P5. External Interrupt trigger edge: P0.0 controlled by PEDGE register.

♦ 1-Level LVD.

Fcpu (Instruction cycle)
Fcpu = Fosc/1, Fpsc/2, Fosc/4, Fosc/8

Powerful instructions
 One clocks per instruction cycle (1T)

Most of instructions are one cycle only.
All ROM area JMP instruction.
All ROM area CALL address instruction.
All ROM area lookup table function (MOVC).

2 interrupt sources

1 internal interrupts: T0 1 external interrupts: INT0

♦ One 8-bit timer. (T0).

T0: Basic timer.

♦ One channel duty/cycle programmable IR output.

♦ Five system clocks

External high clock: RC type up to 8 MHz External high clock: Crystal type up to 8 MHz External low clock: Crystal type 32KHz and 455KHz

Internal high clock: RC type 8MHz Internal low clock: RC type 10KHz(3V)

Four operating modes

Normal mode: Both high and low clock active

Slow mode: Low clock only

Sleep mode: Both high and low clock stop Green mode: Periodical wakeup by timer

Package (Chip form support)

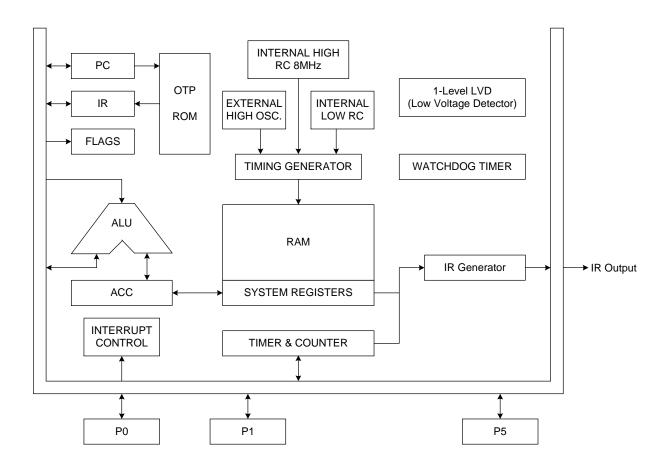
PDIP 20 pin SOP 20 pin SSOP 20 pin SOP 16 pin SOP 14 pin

Features Selection Table

					Os	cillate	or		IR	Wakaun	
CHIP	ROM	RAM	Stack	T0	Ext. 455K	Ext. 4M	Int. 8M	I/O	Output	Wakeup Pin No.	Package
SN8PC01	0.5K*16	32	4	-	V	-	-	16	Fix 38KHz, Normal current	9	PDIP20/SOP20
SN8PC13	2K*16	48	4	>	-	V	1	16	Duty/cycle programmable, Normal current	15	PDIP20/SOP20/ SSOP20
SN8PC20	2K*16	56	4	V	٧	V	٧	18	Duty/cycle programmable, 400mA sink current	16	PDIP20/SOP20/ SSOP20
SN8PC2016	2K*16	56	4	>	V	V	V	14	Duty/cycle programmable, 400mA sink current	12	SOP16
SN8PC2014	2K*16	56	4	V	V	V	٧	12	Duty/cycle programmable, 400mA sink current	10	SOP14



1.2 SYSTEM BLOCK DIAGRAM





1.3 PIN ASSIGNMENT

SN8PC20P (PDIP 20 pins) SN8PC20S (SOP 20 pins) SN8PC20X (SSOP 20 pins)

				=
VDD	1	U	20	VSS
P0.0/INT0	2		19	P5.4/IROUT
P0.1	3		18	P5.0
P0.2/RST/VPP	4		17	P1.7
P0.3/XIN	5		16	P1.6
P0.4/XOUT	6		15	P1.5
P0.5	7		14	P1.4
P0.6	8		13	P1.3
P0.7	9		12	P1.2
P1.0	10		11	P1.1

SN8PC2016S (SOP 16 pins)

VDD	1	U	16	VSS
P0.0/INT0	2		15	P5.4/IROUT
P0.1	3		14	P5.0
P0.2/RST/VPP	4		13	P1.5
P0.3/XIN	5		12	P1.4
P0.4/XOUT	6		11	P1.3
P0.5	7		10	P1.2
P1.0	8		9	P1.1

SN8PC2014S (SOP 14 pins)

VDD	1	U	14	VSS
P0.0/INT0	2		13	P5.4/IROUT
P0.1	3		12	P5.0
P0.2/RST/VPP	4		11	P1.3
P0.3/XIN	5		10	P1.2
P0.4/XOUT	6		9	P1.1
P0.5	7		8	P1.0



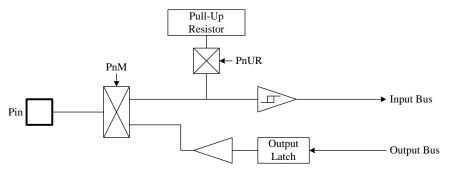
1.4 PIN DESCRIPTIONS

PIN NAME	TYPE	DESCRIPTION			
VDD, VSS	Р	Power supply input pins for digital and analog circuit.			
		RST: System external reset input pin. Schmitt trigger structure, active "low", normal stay to			
P0.2/RST/	I, P	"high".			
VPP	', '	VPP: OTP power input pin in programming mode.			
		P0.2: Input only pin with Schmitt trigger structure and no pull-up resistor.			
		XIN: Oscillator input pin while external oscillator enable (crystal and RC).			
XIN/P0.3	I/O	P0.3: Bi-direction pin. Schmitt trigger structure. Built-in pull-up resistors and level change			
		wake-up function as input mode.			
		XOUT: Oscillator output pin while external crystal enable.			
XOUT/P0.4	I/O	P0.4: Bi-direction pin. Schmitt trigger structure. Built-in pull-up resistors and level change			
		wake-up function as input mode.			
		P0.0: Bi-direction pin. Schmitt trigger structure. Built-in pull-up resistors and level change			
P0.0/INT0	I/O	wake-up function as input mode.			
		INTO: External interrupt 0 input pin.			
P0.1,	I/O	P0: Bi-direction pin. Schmitt trigger structure. Built-in pull-up resistors and level change wake-up			
P0[7:5]		function as input mode.			
P1[7:0]	I/O	P1: Bi-direction pin. Schmitt trigger structure. Built-in pull-up resistors and level change wake-up			
		function controlled by P1W register as input mode.			
P5.0	I/O	P5.0: Bi-direction pin. Schmitt trigger structure. Built-in pull-up resistors as input mode.			
P5.4/IROUT	I/O	P5.4: Bi-direction pin. Schmitt trigger structure. Built-in pull-up resistors as input mode.			
		IROUT: Duty/cycle programmable IR signal output pin.			

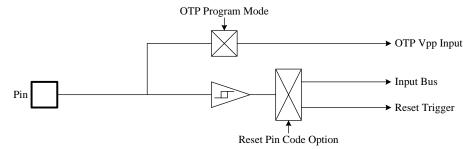


1.5 PIN CIRCUIT DIAGRAMS

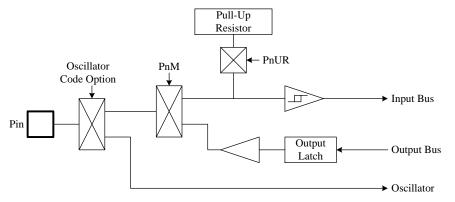
I/O with Schmitt-trigger (ViH=0.7*Vdd, ViL=0.3*Vdd) and Pull-up Resistor(200KΩ@3V):



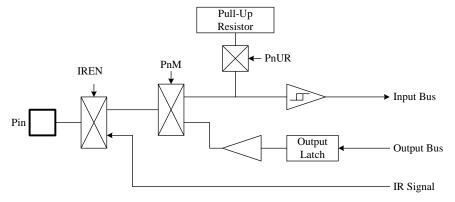
• Input Only with Schmitt-trigger (ViH=0.7*Vdd, ViL=0.3*Vdd) and Vpp High Voltage:



Oscillator shared I/O with Schmitt-trigger (ViH=0.7*Vdd, ViL=0.3*Vdd) and Pull-up Resistor(200KΩ@3V):



• IR output shared I/O with Schmitt-trigger (ViH=0.7*Vdd, ViL=0.3*Vdd) and Pull-up Resistor(200KΩ@3V):





2 CENTRAL PROCESSOR UNIT (CPU)

2.1 PROGRAM MEMORY (ROM)

☞ 2K words ROM

	_	7
0000H	Reset vector	User reset vector Jump to user start address
0001H		,
•	General purpose area	
0007H		
H8000	Interrupt vector	User interrupt vector
0009H		User program
•		
000FH		
0010H		
0011H	General purpose area	
•		
07FCH		End of user program
07FDH		
07FEH	Reserved	
07FFH		J

ROM

The ROM includes Reset vector, Interrupt vector, General purpose area and Reserved area. The Reset vector is program beginning address. The Interrupt vector is the head of interrupt service routine when any interrupt occurring. The General purpose area is main program area including main loop, sub-routines and data table.



2.1.1 RESET VECTOR (0000H)

A one-word vector address area is used to execute system reset.

- Power On Reset (NT0=1, NPD=0).
- Watchdog Reset (NT0=0, NPD=0).
- External Reset (NT0=1, NPD=1).

After power on reset, external reset or watchdog timer overflow reset, then the chip will restart the program from address 0000h and all system registers will be set as default values. It is easy to know reset status from NT0, NPD flags of PFLAG register. The following example shows the way to define the reset vector in the program memory.

; End of program

Example: Defining Reset Vector

ENDP

	ORG JMP 	0 START	; 0000H ; Jump to user program address.
START:	ORG 	10H	; 0010H, The head of user program. ; User program



2.1.2 INTERRUPT VECTOR (0008H)

A 1-word vector address area is used to execute interrupt request. If any interrupt service executes, the program counter (PC) value is stored in stack buffer and jump to 0008h of program memory to execute the vectored interrupt. Users have to define the interrupt vector. The following example shows the way to define the interrupt vector in the program memory.

Note: "PUSH", "POP" instructions save and load ACC/PFLAG without (NT0, NPD). PUSH/POP buffer is a unique buffer and only one level.

> Example: Defining Interrupt Vector. The interrupt service routine is following ORG 8.

.CODE

ORG 0 ; 0000H

JMP START ; Jump to user program address.

• • •

ORG 8 ; Interrupt vector.

PUSH ; Save ACC and PFLAG register to buffers.

..

POP ; Load ACC and PFLAG register from buffers.

RETI ; End of interrupt service routine

. . .

START: ; The head of user program.

.. ; User program

JMP START ; End of user program

• • •

ENDP ; End of program



Example: Defining Interrupt Vector. The interrupt service routine is following user program.

.CODE

ORG 0 : 0000H

JMP START ; Jump to user program address.

ORG 8 ; Interrupt vector.

JMP MY_IRQ ; 0008H, Jump to interrupt service routine address.

ORG 10H

START: ; 0010H, The head of user program.

; User program.

•••

JMP START ; End of user program.

MY_IRQ: ;The head of interrupt service routine.

PUSH ; Save ACC and PFLAG register to buffers.

• • •

POP ; Load ACC and PFLAG register from buffers.

RETI ; End of interrupt service routine.

...

ENDP ; End of program.

- * Note: It is easy to understand the rules of SONIX program from demo programs given above. These points are as following:
 - 1. The address 0000H is a "JMP" instruction to make the program starts from the beginning.
 - 2. The address 0008H is interrupt vector.
 - 3. User's program is a loop routine for main purpose application.



2.1.3 LOOK-UP TABLE DESCRIPTION

In the ROM's data lookup function, Y register is pointed to middle byte address (bit 8~bit 15) and Z register is pointed to low byte address (bit 0~bit 7) of ROM. After MOVC instruction executed, the low-byte data will be stored in ACC and high-byte data stored in R register.

> Example: To look up the ROM data located "TABLE1".

 $\begin{array}{lll} B0MOV & Y, \#TABLE1\$M & ; To set lookup table1's middle address \\ B0MOV & Z, \#TABLE1\$L & ; To set lookup table1's low address. \\ MOVC & ; To lookup data, R = 00H, ACC = 35H \\ \end{array}$

; Increment the index address for next address.

INCMS Z ; Z+1 JMP @F ; Z is not overflow. INCMS Y ; Z overflow (FFH \rightarrow 00), \rightarrow Y=Y+1 NOP :

@ @: MOVC ; To lookup data, R = 51H, ACC = 05H.

TABLE1: DW 0035H ; To define a word (16 bits) data.

DW 5105H

DW 2012H

* Note: The Y register will not increase automatically when Z register crosses boundary from 0xFF to 0x00. Therefore, user must be take care such situation to avoid look-up table errors. If Z register is overflow, Y register must be added one. The following INC_YZ macro shows a simple method to process Y and Z registers automatically.

> Example: INC_YZ macro.

INC_YZ MACRO
INCMS Z ; Z+1

JMP @F ; Not overflow

INCMS Y ; Y+1

NOP ; Not overflow

@@:

ENDM



Example: Modify above example by "INC_YZ" macro.

BOMOV Y, #TABLE1\$M ; To set lookup table1's middle address BOMOV Z, #TABLE1\$L ; To set lookup table1's low address.

MOVC ; To lookup data, R = 00H, ACC = 35H

INC_YZ ; Increment the index address for next address.

@@: MOVC ; To lookup data, R = 51H, ACC = 05H.

TABLE1: DW 0035H ; To define a word (16 bits) data.

DW 5105H DW 2012H

...

The other example of look-up table is to add Y or Z index register by accumulator. Please be careful if "carry" happen.

> Example: Increase Y and Z register by B0ADD/ADD instruction.

B0MOV Y, #TABLE1\$M ; To set lookup table's middle address. B0MOV Z, #TABLE1\$L ; To set lookup table's low address.

B0MOV A, BUF ; Z = Z + BUF. B0ADD Z, A

B0BTS1 FC ; Check the carry flag.

JMP GETDATA ; FC = 0

JMP GETDATA ; FC = 0 INCMS Y ; FC = 1. Y+1.

NOP

GETDATA:

MOVC ; To lookup data. If BUF = 0, data is 0x0035

; If BUF = 1, data is 0x5105 ; If BUF = 2, data is 0x2012

TABLE1: DW 0035H ; To define a word (16 bits) data.

DW 5105H DW 2012H

...



2.1.4 JUMP TABLE DESCRIPTION

The jump table operation is one of multi-address jumping function. Add low-byte program counter (PCL) and ACC value to get one new PCL. If PCL is overflow after PCL+ACC, PCH adds one automatically. The new program counter (PC) points to a series jump instructions as a listing table. It is easy to make a multi-jump program depends on the value of the accumulator (A).

- Note: PCH only support PC up counting result and doesn't support PC down counting. When PCL is carry after PCL+ACC, PCH adds one automatically. If PCL borrow after PCL-ACC, PCH keeps value and not change.
- Example: Jump table.

```
ORG
            0X0100
                            ; The jump table is from the head of the ROM boundary
BOADD
            PCL, A
                            ; PCL = PCL + ACC, PCH + 1 when PCL overflow occurs.
JMP
            A0POINT
                             ; ACC = 0, jump to A0POINT
JMP
                             ; ACC = 1, jump to A1POINT
            A1POINT
JMP
                             ; ACC = 2, jump to A2POINT
            A2POINT
JMP
            A3POINT
                             ; ACC = 3, jump to A3POINT
```

SONIX provides a macro for safe jump table function. This macro will check the ROM boundary and move the jump table to the right position automatically. The side effect of this macro maybe wastes some ROM size.

Example: If "jump table" crosses over ROM boundary will cause errors.

```
@JMP_A MACRO VAL
IF (($+1)!& 0XFF00)!!= (($+(VAL))!& 0XFF00)
JMP ($|0XFF)
ORG ($|0XFF)
ENDIF
B0ADD PCL, A
ENDM
```

- Note: "VAL" is the number of the jump table listing number.
- Example: "@JMP A" application in SONIX macro file called "MACRO3.H".

```
B0MOV
            A, BUF0
                             ; "BUF0" is from 0 to 4.
@JMP_A
                             The number of the jump table listing is five.
            5
                             ; ACC = 0, jump to A0POINT
            A0POINT
JMP
JMP
            A1POINT
                             ; ACC = 1, jump to A1POINT
JMP
            A2POINT
                             ; ACC = 2, jump to A2POINT
JMP
            A3POINT
                             ; ACC = 3, jump to A3POINT
JMP
            A4POINT
                             ; ACC = 4, jump to A4POINT
```



If the jump table position is across a ROM boundary (0x00FF~0x0100), the "@JMP_A" macro will adjust the jump table routine begin from next RAM boundary (0x0100).

> Example: "@JMP_A" operation.

; Before compiling program.

ROM	address
------------	---------

	B0MOV	A, BUF0	; "BUF0" is from 0 to 4.
	@JMP_A	5	; The number of the jump table listing is five.
0X00FD	JMP	A0POINT	; ACC = 0, jump to A0POINT
0X00FE	JMP	A1POINT	; ACC = 1, jump to A1POINT
0X00FF	JMP	A2POINT	; ACC = 2, jump to A2POINT
0X0100	JMP	A3POINT	; ACC = 3, jump to A3POINT
0X0101	JMP	A4POINT	; ACC = 4, jump to A4POINT

; After compiling program.

R	\cap	N٨	addr	220
т.	. ,	11//	1000	

ROW address			
	B0MOV	A, BUF0	; "BUF0" is from 0 to 4.
	@JMP_A	5	; The number of the jump table listing is five.
0X0100	JMP	A0POINT	; ACC = 0, jump to A0POINT
0X0101	JMP	A1POINT	; ACC = 1, jump to A1POINT
0X0102	JMP	A2POINT	; ACC = 2, jump to A2POINT
0X0103	JMP	A3POINT	; ACC = 3, jump to A3POINT
0X0104	JMP	A4POINT	; ACC = 4, jump to A4POINT



2.1.5 CHECKSUM CALCULATION

The last ROM address are reserved area. User should avoid these addresses (last address) when calculate the Checksum value.

Example: The demo program shows how to calculated Checksum from 00H to the end of user's code.

MOV A,#END_USER_CODE\$L

B0MOV END_ADDR1, A ; Save low end address to end_addr1

MOV A,#END USER CODE\$M

BOMOV END_ADDR2, A ; Save middle end address to end_addr2

 CLR
 Y
 ; Set Y to 00H

 CLR
 Z
 ; Set Z to 00H

@@:

MOVC

BOBSET FC ; Clear C flag ADD DATA1, A ; Add A to Data1

MOV A, R

ADC DATA2, A ; Add R to Data2

JMP END CHECK ; Check if the YZ address = the end of code

AAA:

INCMS Z; Z=Z+1

JMP @B ; If Z != 00H calculate to next address

JMP Y_ADD_1 ; If Z = 00H increase Y

END_CHECK:

MOV A, END_ADDR1

CMPRS A, Z ; Check if Z = low end address

JMP AAA ; If Not jump to checksum calculate

MOV A, END_ADDR2

CMPRS A, Y ; If Yes, check if Y = middle end address

JMP AAA ; If Not jump to checksum calculate

JMP CHECKSUM_END ; If Yes checksum calculated is done.

Y ADD 1:

INCMS Y ; Increase Y

NOP

JMP @B ; Jump to checksum calculate

CHECKSUM_END:

• • • •

...

END_USER_CODE: ; Label of program end



2.2 DATA MEMORY (RAM)

56 X 8-bit RAM

	Address	RAM Location]
	000h		RAM Bank 0
	" " 037h	General Purpose Area	
BANK 0	080h "	System Register	080h~0FFh of Bank 0 store system registers (128 bytes).
	0FFh		End of Bank 0

Sonix provides "Bank 0" type instructions (e.g. b0mov, b0add, b0bts1, b0bset...) to control Bank 0 RAM directly.

2.2.1 SYSTEM REGISTER

SYSTEM REGISTER TABLE 2.2.1.1

	0	1	2	3	4	5	6	7	8	9	Α	В	С	D	Е	F
8	L	Н	R	Z	Y	-	PFLAG	-	-	-	-	-	-	-	-	-
9	-	=	-	-	-	-	-	1	-	-	-	-	1	-	-	-
Α	1	-	•	ı	-	-	•	1	-	-	-	-	ı	-	-	-
В	-	=	-	-	-	-	-	-	P0M	-	-	-	-	-	-	PEDGE
С	P1W	P1M	=	-	-	P5M	-	-	INTRQ	INTEN	OSCM	-	WDTR	IRR	PCL	PCH
D	P0	P1	-	1	-	P5	-	-	TOM	T0C	IRM	IRC	-	-	-	STKP
Е	P0UR	P1UR	-	ı	-	P5UR	@HL	@YZ	IRD	-	-	-	-	-	-	-
F	-	=	-	-	-	-	-	-	STK3L	STK3H	STK2L	STK2H	STK1L	STK1H	STK0L	STK0H

SYSTEM REGISTER DESCRIPTION 2.2.1.2

H, L = Working, @HL addressing register.

R = Working register and ROM look-up data buffer.

PnM = Port n input/output mode register.

INTRQ = Interrupt request register.

OSCM = Oscillator mode register.

IRR = IR counter auto-reload data buffer.

Pn = Port n data buffer.

TOC = T0 counting register.

IRC = IR counting register.

PnUR = Port n pull-up resister control register.

@YZ = RAM YZ indirect addressing index pointer.

STK0~STK3 = Stack 0 ~ stack 3 buffer.

Y, Z = Working, @YZ and ROM addressing register.

PFLAG = ROM page and special flag register.

PEDGE = P0.0 edge direction register. INTEN = Interrupt enable register.

WDTR = Watchdog timer clear register.

PCH, PCL = Program counter.

T0M = T0 mode register. IRM = IR mode register.

STKP = Stack pointer buffer.

@HL = RAM HL indirect addressing index pointer.

IRD = IR duty control register.



2.2.1.3 BIT DEFINITION of SYSTEM REGISTER

Address	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W	Remarks
080H	LBIT7	LBIT6	LBIT5	LBIT4	LBIT3	LBIT2	LBIT1	LBIT0	R/W	L
081H	HBIT7	HBIT6	HBIT5	HBIT4	HBIT3	HBIT2	HBIT1	HBIT0	R/W	Н
082H	RBIT7	RBIT6	RBIT5	RBIT4	RBIT3	RBIT2	RBIT1	RBIT0	R/W	R
083H	ZBIT7	ZBIT6	ZBIT5	ZBIT4	ZBIT3	ZBIT2	ZBIT1	ZBIT0	R/W	Z
084H	YBIT7	YBIT6	YBIT5	YBIT4	YBIT3	YBIT2	YBIT1	YBIT0	R/W	Y
086H	NT0	NPD				С	DC	Z	R/W	PFLAG
0B8H	P07M	P06M	P05M	P04M	P03M		P01M	P00M	R/W	P0M
0BFH				P00G1	P00G0				R/W	PEDGE
0C0H	P17W	P16W	P15W	P14W	P13W	P12W	P11W	P10W	W	P1W
0C1H	P17M	P16M	P15M	P14M	P13M	P12M	P11M	P10M	R/W	P1M
0C5H				P54M				P50M	R/W	P5M
0C8H				T0IRQ				P00IRQ	R/W	INTRQ
0C9H				TOIEN				P00IEN	R/W	INTEN
0CAH				CPUM1	CPUM0	CLKMD	STPHX		R/W	OSCM
0CCH	WDTR7	WDTR6	WDTR5	WDTR4	WDTR3	WDTR2	WDTR1	WDTR0	W	WDTR
0CDH	IRR7	IRR6	IRR5	IRR4	IRR3	IRR2	IRR1	IRR0	W	IRR
0CEH	PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0	R/W	PCL
0CFH						PC10	PC9	PC8	R/W	PCH
0D0H	P07	P06	P05	P04	P03	P02	P01	P00	R/W	P0
0D1H	P17	P16	P15	P14	P13	P12	P11	P10	R/W	P1
0D5H				P54				P50	R/W	P5
0D8H	T0ENB	T0rate2	T0rate1	T0rate0					R/W	TOM
0D9H	T0C7	T0C6	T0C5	T0C4	T0C3	T0C2	T0C1	T0C0	R/W	T0C
0DAH							IREN	CREN	R/W	IRM
0DBH	IRC7	IRC6	IRC5	IRC4	IRC3	IRC2	IRC1	IRC0	R/W	IRC
0DFH	GIE						STKPB1	STKPB0	R/W	STKP
0E0H	P07R	P06R	P05R	P04R	P03R		P01R	P00R	W	P0UR
0E1H	P17R	P16R	P15R	P14R	P13R	P12R	P11R	P10R	W	P1UR
0E5H				P54R				P50R	W	P5UR
0E6H	@HL7	@HL6	@HL5	@HL4	@HL3	@HL2	@HL1	@HL0	R/W	@HL
0E7H	@YZ7	@YZ6	@YZ5	@YZ4	@YZ3	@YZ2	@YZ1	@YZ0	R/W	@YZ
0E8H	IRD7	IRD6	IRD5	IRD4	IRD3	IRD2	IRD1	IRD0	W	IRD
0F8H	S3PC7	S3PC6	S3PC5	S3PC4	S3PC3	S3PC2	S3PC1	S3PC0	R/W	STK3L
0F9H						S3PC10	S3PC9	S3PC8	R/W	STK3H
0FAH	S2PC7	S2PC6	S2PC5	S2PC4	S2PC3	S2PC2	S2PC1	S2PC0	R/W	STK2L
0FBH						S2PC10	S2PC9	S2PC8	R/W	STK2H
0FCH	S1PC7	S1PC6	S1PC5	S1PC4	S1PC3	S1PC2	S1PC1	S1PC0	R/W	STK1L
0FDH				-		S1PC10	S1PC9	S1PC8	R/W	STK1H
0FEH	S0PC7	S0PC6	S0PC5	S0PC4	S0PC3	S0PC2	S0PC1	S0PC0	R/W	STK0L
0FFH						S0PC10	S0PC9	S0PC8	R/W	STK0H

* Note:

- 1. To avoid system error, make sure to put all the "0" and "1" as it indicates in the above table.
- 2. All of register names had been declared in SN8ASM assembler.
- 3. One-bit name had been declared in SN8ASM assembler with "F" prefix code.
- 4. "b0bset", "b0bclr", "bset", "bclr" instructions are only available to the "R/W" registers.



2.2.2 ACCUMULATOR

The ACC is an 8-bit data register responsible for transferring or manipulating data between ALU and data memory. If the result of operating is zero (Z) or there is carry (C or DC) occurrence, then these flags will be set to PFLAG register. ACC is not in data memory (RAM), so ACC can't be access by "B0MOV" instruction during the instant addressing mode.

> Example: Read and write ACC value.

; Read ACC data and store in BUF data memory.

MOV BUF, A

; Write a immediate data into ACC.

MOV A, #0FH

; Write ACC data from BUF data memory.

MOV A, BUF

; or

B0MOV A, BUF

The system doesn't store ACC and PFLAG value when interrupt executed. ACC and PFLAG data must be saved to other data memories. "PUSH", "POP" save and load ACC, PFLAG data into buffers.

> Example: Protect ACC and working registers.

INT_SERVICE:

PUSH ; Save ACC and PFLAG to buffers.

. . .

POP ; Load ACC and PFLAG from buffers.

RETI ; Exit interrupt service vector



2.2.3 PROGRAM FLAG

The PFLAG register contains the arithmetic status of ALU operation, system reset status and LVD detecting status. NT0, NPD bits indicate system reset status including power on reset, LVD reset, reset by external pin active and watchdog reset. C, DC, Z bits indicate the result status of ALU operation.

086H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
PFLAG	NT0	NPD	-	-	-	С	DC	Z
Read/Write	R/W	R/W	-	-	-	R/W	R/W	R/W
After reset	-	-	-	-	-	0	0	0

Bit [7:6] NT0, NPD: Reset status flag.

NT0	NPD	Reset Status
0	0	Watch-dog time out
0	1	Reserved
1	0	Reset by LVD
1	1	Reset by external Reset Pin

Bit 2 C: Carry flag

- 1 = Addition with carry, subtraction without borrowing, rotation with shifting out logic "1", comparison result ≥ 0.
- 0 = Addition without carry, subtraction with borrowing signal, rotation with shifting out logic "0", comparison result < 0.

Bit 1 **DC:** Decimal carry flag

- 1 = Addition with carry from low nibble, subtraction without borrow from high nibble.
- 0 = Addition without carry from low nibble, subtraction with borrow from high nibble.

Bit 0 Z: Zero flag

- 1 = The result of an arithmetic/logic/branch operation is zero.
- 0 = The result of an arithmetic/logic/branch operation is not zero.

Note: Refer to instruction set table for detailed information of C, DC and Z flags.



2.2.4 PROGRAM COUNTER

The program counter (PC) is a 11-bit binary counter separated into the high-byte 3 and the low-byte 8 bits. This counter is responsible for pointing a location in order to fetch an instruction for kernel circuit. Normally, the program counter is automatically incremented with each instruction during program execution.

Besides, it can be replaced with specific address by executing CALL or JMP instruction. When JMP or CALL instruction is executed, the destination address will be inserted to bit 0 ~ bit 10.

	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
PC	-	-	-	-	1	PC10	PC9	PC8	PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0
After reset	ı	•	•			0	0	0	0	0	0	0	0	0	0	0
	PCH											PC	CL			

ONE ADDRESS SKIPPING

There are nine instructions (CMPRS, INCS, INCMS, DECS, DECMS, BTS0, BTS1, B0BTS0, B0BTS1) with one address skipping function. If the result of these instructions is true, the PC will add 2 steps to skip next instruction.

If the condition of bit test instruction is true, the PC will add 2 steps to skip next instruction.

B0BTS1 FC ; To skip, if Carry_flag = 1 JMP C0STEP ; Else jump to C0STEP.

...

COSTEP: NOP

B0MOV A, BUF0 ; Move BUF0 value to ACC. **B0BTS0** FZ ; To skip, if Zero flag = 0.

JMP C1STEP ; Else jump to C1STEP.

- - -

...

C1STEP: NOP

If the ACC is equal to the immediate data or memory, the PC will add 2 steps to skip next instruction.

CMPRS A, #12H ; To skip, if ACC = 12H.

JMP COSTEP ; Else jump to COSTEP.

• • •

COSTEP: NOP



If the destination increased by 1, which results overflow of 0xFF to 0x00, the PC will add 2 steps to skip next instruction.

INCS instruction:

INCS BUF0

JMP COSTEP ; Jump to COSTEP if ACC is not zero.

. . .

COSTEP: NOP

INCMS instruction:

INCMS BUF0

JMP COSTEP ; Jump to COSTEP if BUF0 is not zero.

• • •

COSTEP: NOP

If the destination decreased by 1, which results underflow of 0x01 to 0x00, the PC will add 2 steps to skip next instruction.

DECS instruction:

DECS BUF0

JMP COSTEP ; Jump to COSTEP if ACC is not zero.

• • •

COSTEP: NOP

DECMS instruction:

DECMS BUF0

JMP COSTEP ; Jump to COSTEP if BUF0 is not zero.

• • •

COSTEP: NOP



MULTI-ADDRESS JUMPING

Users can jump around the multi-address by either JMP instruction or ADD M, A instruction (M = PCL) to activate multi-address jumping function. Program Counter supports "ADD M,A", "ADC M,A" and "B0ADD M,A" instructions for carry to PCH when PCL overflow automatically. For jump table or others applications, users can calculate PC value by the three instructions and don't care PCL overflow problem.

Note: PCH only support PC up counting result and doesn't support PC down counting. When PCL is carry after PCL+ACC, PCH adds one automatically. If PCL borrow after PCL-ACC, PCH keeps value and not change.

Example: If PC = 0323H (PCH = 03H, PCL = 23H)

PC = 0323H

MOV A, #28H

B0MOV PCL, A ; Jump to address 0328H

...

; PC = 0328H

MOV A, #00H

BOMOV PCL, A ; Jump to address 0300H

. . .

> Example: If PC = 0323H (PCH = 03H, PCL = 23H)

PC = 0323H

BOADD PCL, A ; PCL = PCL + ACC, the PCH cannot be changed.

• •

• •



2.2.5 H, L REGISTERS

The H and L registers are the 8-bit buffers. There are two major functions of these registers.

- Can be used as general working registers
- Can be used as RAM data pointers with @HL register

081H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Н	HBIT7	HBIT6	HBIT5	HBIT4	HBIT3	HBIT2	HBIT1	HBIT0
Read/Write	R/W							
After reset	ı	ı	ı	ı	ı	1	-	-

080H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
L	LBIT7	LBIT6	LBIT5	LBIT4	LBIT3	LBIT2	LBIT1	LBIT0
Read/Write	R/W							
After reset	-	-	-	-	-	-	-	-

Example: If want to read a data from RAM address 20H of bank_0, it can use indirectly addressing mode to access data as following.

B0MOV H, #00H ; To set RAM bank 0 for H register B0MOV L, #20H ; To set location 20H for L register

B0MOV A, @HL ; To read a data into ACC

> Example: Clear general-purpose data memory area of bank 0 using @HL register.

CLR H ; H = 0, bank 0

B0MOV L, #07FH ; L = 7FH, the last address of the data memory area

CLR_HL_BUF:

CLR @HL ; Clear @HL to be zero

DECMS L ; L - 1, if L = 0, finish the routine

JMP CLR_HL_BUF ; Not zero

CLR @HL

END_CLR: ; End of clear general purpose data memory area of bank 0

...



2.2.6 Y, Z REGISTERS

The Y and Z registers are the 8-bit buffers. There are three major functions of these registers.

- Can be used as general working registers
- Can be used as RAM data pointers with @YZ register
- Can be used as ROM data pointer with the MOVC instruction for look-up table

084H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Υ	YBIT7	YBIT6	YBIT5	YBIT4	YBIT3	YBIT2	YBIT1	YBIT0
Read/Write	R/W							
After reset	-	-	-	-	-	-	-	-

083H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Z	ZBIT7	ZBIT6	ZBIT5	ZBIT4	ZBIT3	ZBIT2	ZBIT1	ZBIT0
Read/Write	R/W							
After reset	-	-	-	-	-	-	-	-

Example: Uses Y, Z register as the data pointer to access data in the RAM address 025H of bank0.

B0MOV Y, #00H ; To set RAM bank 0 for Y register B0MOV Z, #25H ; To set location 25H for Z register

B0MOV A, @YZ ; To read a data into ACC

> Example: Uses the Y, Z register as data pointer to clear the RAM data.

B0MOV Y, #0 ; Y = 0, bank 0

B0MOV Z, #07FH ; Z = 7FH, the last address of the data memory area

CLR_YZ_BUF:

CLR @YZ ; Clear @YZ to be zero

DECMS Z ; Z - 1, if Z = 0, finish the routine

JMP CLR_YZ_BUF ; Not zero

CLR @YZ

END_CLR: ; End of clear general purpose data memory area of bank 0

.



2.2.7 R REGISTER

R register is an 8-bit buffer. There are two major functions of the register.

- Can be used as working register
- For store high-byte data of look-up table
 (MOVC instruction executed, the high-byte data of specified ROM address will be stored in R register and the
 low-byte data will be stored in ACC).

082H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
R	RBIT7	RBIT6	RBIT5	RBIT4	RBIT3	RBIT2	RBIT1	RBIT0
Read/Write	R/W							
After reset	-	-	-	-	-	-	-	-

Note: Please refer to the "LOOK-UP TABLE DESCRIPTION" about R register look-up table application.



ADDRESSING MODE 2.3

2.3.1 IMMEDIATE ADDRESSING MODE

The immediate addressing mode uses an immediate data to set up the location in ACC or specific RAM.

Example: Move the immediate data 12H to ACC.

MOV A, #12H : To set an immediate data 12H into ACC.

Example: Move the immediate data 12H to R register.

B0MOV R, #12H ; To set an immediate data 12H into R register.

Note: In immediate addressing mode application, the specific RAM must be 0x80~0x87 working register.

2.3.2 DIRECTLY ADDRESSING MODE

The directly addressing mode moves the content of RAM location in or out of ACC.

Example: Move 0x12 RAM location data into ACC.

B0MOV A, 12H ; To get a content of RAM location 0x12 of bank 0 and save in

ACC.

Example: Move ACC data into 0x12 RAM location.

; To get a content of ACC and save in RAM location 12H of **B0MOV** 12H. A

bank 0.

2.3.3 INDIRECTLY ADDRESSING MODE

The indirectly addressing mode is to access the memory by the data pointer registers (H/L, Y/Z).

Example: Indirectly addressing mode with @HL register

B0MOV H, #0 ; To clear H register to access RAM bank 0. **B0MOV** ; To set an immediate data 12H into L register. L. #12H

B0MOV ; Use data pointer @HL reads a data from RAM location A. @HL

; 012H into ACC.

Example: Indirectly addressing mode with @YZ register

B0MOV Y, #0 ; To clear Y register to access RAM bank 0. **B0MOV** ; To set an immediate data 12H into Z register. Z, #12H

B0MOV

A, @YZ ; Use data pointer @YZ reads a data from RAM location

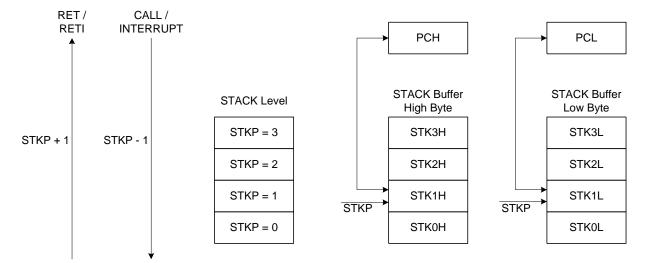
; 012H into ACC.



2.4 STACK OPERATION

2.4.1 OVERVIEW

The stack buffer has 4-level. These buffers are designed to push and pop up program counter's (PC) data when interrupt service routine and "CALL" instruction are executed. The STKP register is a pointer designed to point active level in order to push or pop up data from stack buffer. The STKnH and STKnL are the stack buffers to store program counter (PC) data.





2.4.2 STACK REGISTERS

The stack pointer (STKP) is a 2-bit register to store the address used to access the stack buffer, 9-bit data memory (STKnH and STKnL) set aside for temporary storage of stack addresses.

The two stack operations are writing to the top of the stack (push) and reading from the top of stack (pop). Push operation decrements the STKP and the pop operation increments each time. That makes the STKP always point to the top address of stack buffer and write the last program counter value (PC) into the stack buffer.

The program counter (PC) value is stored in the stack buffer before a CALL instruction executed or during interrupt service routine. Stack operation is a LIFO type (Last in and first out). The stack pointer (STKP) and stack buffer (STKnH and STKnL) are located in the system register area bank 0.

0DFH	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
STKP	GIE	ı	-	-	-	•	STKPB1	STKPB0
Read/Write	R/W	-	-	-	-	-	R/W	R/W
After reset	0	-	-	-	-	-	1	1

Bit[2:0] **STKPBn:** Stack pointer (n = $0 \sim 1$)

Bit 7 **GIE:** Global interrupt control bit.

0 = Disable.

1 = Enable. Please refer to the interrupt chapter.

Example: Stack pointer (STKP) reset, we strongly recommended to clear the stack pointers in the beginning of the program.

MOV A, #00000011B B0MOV STKP, A

0F0H~0F8H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
STKnH	-	-	-	-	-	SnPC10	SnPC9	SnPC8
Read/Write	-	-	-	-	-	R/W	R/W	R/W
After reset	-	-	-	-	-	0	0	0

0F0H~0F8H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
STKnL	SnPC7	SnPC6	SnPC5	SnPC4	SnPC3	SnPC2	SnPC1	SnPC0
Read/Write	R/W							
After reset	0	0	0	0	0	0	0	0

STKn = STKnH, STKnL $(n = 3 \sim 0)$



2.4.3 STACK OPERATION EXAMPLE

The two kinds of Stack-Save operations refer to the stack pointer (STKP) and write the content of program counter (PC) to the stack buffer are CALL instruction and interrupt service. Under each condition, the STKP decreases and points to the next available stack location. The stack buffer stores the program counter about the op-code address. The Stack-Save operation is as the following table.

Stack Level	STKP F	Register	Stack	Buffer	Dosorintion	
Stack Level	STKPB1	STKPB0	High Byte	Low Byte	Description	
0	1	1	Free	Free	=	
1	1	0	STK0H	STK0L	=	
2	0	1	STK1H	STK1L	=	
3	0	0	STK2H	STK2L	-	
4	1	1	STK3H	STK3L	=	
> 4	1	0	-	-	Stack Over, error	

There are Stack-Restore operations correspond to each push operation to restore the program counter (PC). The RETI instruction uses for interrupt service routine. The RET instruction is for CALL instruction. When a pop operation occurs, the STKP is incremented and points to the next free stack location. The stack buffer restores the last program counter (PC) to the program counter registers. The Stack-Restore operation is as the following table.

Stack Level	STKP F	Register	Stack	Buffer	Docorintion	
Stack Level	STKPB1	STKPB0	High Byte	Low Byte	Description	
4	1	1	STK3H	STK3L	-	
3	0	0	STK2H	STK2L	-	
2	0	1	STK1H	STK1L	-	
1	1	0	STK0H	STK0L	-	
0	1	1	Free	Free	-	



2.5 CODE OPTION TABLE

The code option is the system hardware configurations including oscillator type, watchdog timer operation, reset pin option and OTP ROM security control. The code option items are as following table:

Code Option	Content	Function Description					
	IHRC_8M	High speed internal 8MHz RC. XIN/XOUT pins are bi-direction GPIO mode.					
	RC	Low cost RC for external high clock oscillator. XIN pin is connected to RC oscillator. XOUT pin is bi-direction GPIO mode.					
		Low frequency 32KHz and 455KHz, power saving crystal for external high clock oscillator.					
High_Clk	455K X'tal	32KHz: XIN connects 20pF capacitor, XOUT connects 20pF capacitor.					
		455KHz: XIN connects 47pF capacitor, XOUT connects 20pF capacitor.					
	8M X'tal	High speed crystal/resonator (e.g. 8MHz) for external high clock oscillator.					
	4M X'tal	Standard crystal /resonator (e.g. 4M) for external high clock oscillator.					
	Fhosc/1	Instruction cycle is oscillator clock.					
Fcpu	Fhosc/2	Instruction cycle is 2 oscillator clocks.					
Гори	Fhosc/4	Instruction cycle is 4 oscillator clocks.					
	Fhosc/8	Instruction cycle is 8 oscillator clocks.					
	Always_On	Watchdog timer is always on enable even in power down and green mode.					
Watch_Dog	Enable	Enable watchdog timer. Watchdog timer stops in power down mode and green mode.					
	Disable	Disable Watchdog function.					
Doost Din	Enable External reset pin.						
Reset_Pin	P02	Enable P0.2 input only without pull-up resister.					
Security	Enable	Enable ROM code Security function.					
Security	Disable	Disable ROM code Security function.					

2.5.1 Reset_Pin code option

The reset pin is shared with general input only pin controlled by code option.

- Reset: The reset pin is external reset function. When falling edge trigger occurring, the system will be reset.
- P02: Set reset pin to general input only pin (P0.2). The external reset function is disabled and the pin is input pin.

2.5.2 Security code option

Security code option is OTP ROM protection. When enable security code option, the ROM code is secured and not dumped complete ROM contents.



3 RESET

3.1 OVERVIEW

The system would be reset in three conditions as following.

- Power on reset
- Watchdog reset
- Brown out reset
- External reset (only supports external reset pin enable situation)

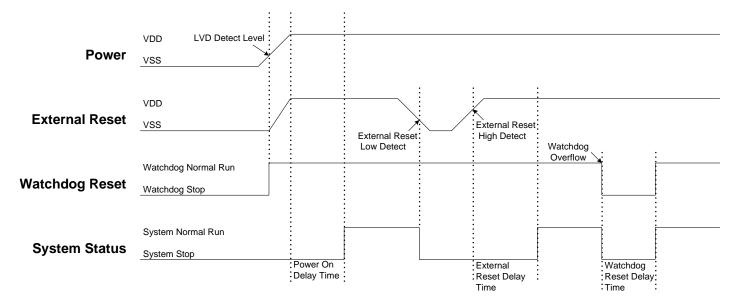
When any reset condition occurs, all system registers keep initial status, program stops and program counter is cleared. After reset status released, the system boots up and program starts to execute from ORG 0. The NTO, NPD flags indicate system reset status. The system can depend on NTO, NPD status and go to different paths by program.

086H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
PFLAG	NT0	NPD	-	-	-	С	DC	Z
Read/Write	R/W	R/W	-	-	-	R/W	R/W	R/W
After reset	-	-	-	-	-	0	0	0

Bit [7:6] NT0, NPD: Reset status flag.

NT0	NPD	Condition	Description
0	0	Watchdog reset	Watchdog timer overflow.
0	1	Reserved	-
1	0	Power on reset and LVD reset.	Power voltage is lower than LVD detecting level.
1	1	External reset	External reset pin detect low level status.

Finishing any reset sequence needs some time. The system provides complete procedures to make the power on reset successful. For different oscillator types, the reset time is different. That causes the VDD rise rate and start-up time of different oscillator is not fixed. RC type oscillator's start-up time is very short, but the crystal type is longer. Under client terminal application, users have to take care the power on reset time for the master terminal requirement. The reset timing diagram is as following.





3.2 POWER ON RESET

The power on reset depend no LVD operation for most power-up situations. The power supplying to system is a rising curve and needs some time to achieve the normal voltage. Power on reset sequence is as following.

- **Power-up:** System detects the power voltage up and waits for power stable.
- External reset (only external reset pin enable): System checks external reset pin status. If external reset pin is not high level, the system keeps reset status and waits external reset pin released.
- System initialization: All system registers is set as initial conditions and system is ready.
- Oscillator warm up: Oscillator operation is successfully and supply to system clock.
- Program executing: Power on sequence is finished and program executes from ORG 0.

3.3 WATCHDOG RESET

Watchdog reset is a system protection. In normal condition, system works well and clears watchdog timer by program. Under error condition, system is in unknown situation and watchdog can't be clear by program before watchdog timer overflow. Watchdog timer overflow occurs and the system is reset. After watchdog reset, the system restarts and returns normal mode. Watchdog reset sequence is as following.

- Watchdog timer status: System checks watchdog timer overflow status. If watchdog timer overflow occurs, the system is reset.
- System initialization: All system registers is set as initial conditions and system is ready.
 - Oscillator warm up: Oscillator operation is successfully and supply to system clock.
- **Program executing:** Power on sequence is finished and program executes from ORG 0.

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- Watchdog timer status: System checks watchdog timer overflow status. If watchdog timer overflow occurs, the system is reset.
- System initialization: All system registers is set as initial conditions and system is ready.
- Oscillator warm up: Oscillator operation is successfully and supply to system clock.
- Program executing: Power on sequence is finished and program executes from ORG 0.

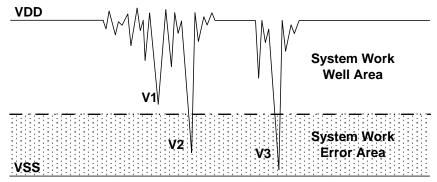
Watchdog timer application note is as following.

- Before clearing watchdog timer, check I/O status and check RAM contents can improve system error.
- Don't clear watchdog timer in interrupt vector and interrupt service routine. That can improve main routine fail.
- Clearing watchdog timer program is only at one part of the program. This way is the best structure to enhance the watchdog timer function.
- Note: Please refer to the "WATCHDOG TIMER" about watchdog timer detail information.



3.4 BROWN OUT RESET

The brown out reset is a power dropping condition. The power drops from normal voltage to low voltage by external factors (e.g. EFT interference or external loading changed). The brown out reset would make the system not work well or executing program error.



Brown Out Reset Diagram

The power dropping might through the voltage range that's the system dead-band. The dead-band means the power range can't offer the system minimum operation power requirement. The above diagram is a typical brown out reset diagram. There is a serious noise under the VDD, and VDD voltage drops very deep. There is a dotted line to separate the system working area. The above area is the system work well area. The below area is the system work error area called dead-band. V1 doesn't touch the below area and not effect the system operation. But the V2 and V3 is under the below area and may induce the system error occurrence. Let system under dead-band includes some conditions.

DC application:

The power source of DC application is usually using battery. When low battery condition and MCU drive any loading, the power drops and keeps in dead-band. Under the situation, the power won't drop deeper and not touch the system reset voltage. That makes the system under dead-band.

AC application:

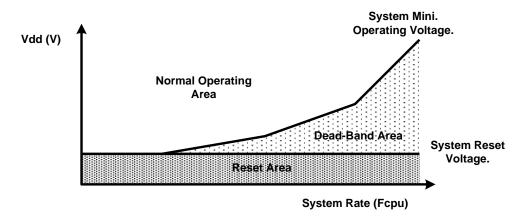
In AC power application, the DC power is regulated from AC power source. This kind of power usually couples with AC noise that makes the DC power dirty. Or the external loading is very heavy, e.g. driving motor. The loading operating induces noise and overlaps with the DC power. VDD drops by the noise, and the system works under unstable power situation.

The power on duration and power down duration are longer in AC application. The system power on sequence protects the power on successful, but the power down situation is like DC low battery condition. When turn off the AC power, the VDD drops slowly and through the dead-band for a while.



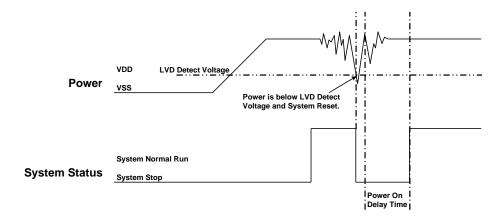
3.4.1 THE SYSTEM OPERATING VOLTAGE

To improve the brown out reset needs to know the system minimum operating voltage which is depend on the system executing rate and power level. Different system executing rates have different system minimum operating voltage. The electrical characteristic section shows the system voltage to executing rate relationship.



Normally the system operation voltage area is higher than the system reset voltage to VDD, and the reset voltage is decided by LVD detect level. The system minimum operating voltage rises when the system executing rate upper even higher than system reset voltage. The dead-band definition is the system minimum operating voltage above the system reset voltage.

3.4.2 LOW VOLTAGE DETECTOR (LVD)



The LVD (low voltage detector) is built-in Sonix 8-bit MCU to be brown out reset protection. When the VDD drops and is below LVD detect voltage, the LVD would be triggered, and the system is reset. The LVD detect level is different by each MCU. The LVD voltage level is a point of voltage and not easy to cover all dead-band range. Using LVD to improve brown out reset is depend on application requirement and environment. If the power variation is very deep, violent and trigger the LVD, the LVD can be the protection. If the power variation can touch the LVD detect level and make system work error, the LVD can't be the protection and need to other reset methods. More detail LVD information is in the electrical characteristic section.



3.4.3 BROWN OUT RESET IMPROVEMENT

How to improve the brown reset condition? There are some methods to improve brown out reset as following.

- LVD reset
- Watchdog reset
- Reduce the system executing rate
- External reset circuit. (Zener diode reset circuit, Voltage bias reset circuit, External reset IC)

* Note:

- 1. The "Zener diode reset circuit", "Voltage bias reset circuit" and "External reset IC" can completely improve the brown out reset, DC low battery and AC slow power down conditions.
- 2. For AC power application and enhance EFT performance, the system clock is 4MHz/4 (1 mips) and use external reset (" Zener diode reset circuit", "Voltage bias reset circuit", "External reset IC"). The structure can improve noise effective and get good EFT characteristic.

Watchdog reset:

The watchdog timer is a protection to make sure the system executes well. Normally the watchdog timer would be clear at one point of program. Don't clear the watchdog timer in several addresses. The system executes normally and the watchdog won't reset system. When the system is under dead-band and the execution error, the watchdog timer can't be clear by program. The watchdog is continuously counting until overflow occurrence. The overflow signal of watchdog timer triggers the system to reset, and the system return to normal mode after reset sequence. This method also can improve brown out reset condition and make sure the system to return normal mode. If the system reset by watchdog and the power is still in dead-band, the system reset sequence won't be successful and the system stays in reset status until the power return to normal range.

Reduce the system executing rate:

If the system rate is fast and the dead-band exists, to reduce the system executing rate can improve the dead-band. The lower system rate is with lower minimum operating voltage. Select the power voltage that's no dead-band issue and find out the mapping system rate. Adjust the system rate to the value and the system exits the dead-band issue. This way needs to modify whole program timing to fit the application requirement.

External reset circuit:

The external reset methods also can improve brown out reset and is the complete solution. There are three external reset circuits to improve brown out reset including "Zener diode reset circuit", "Voltage bias reset circuit" and "External reset IC". These three reset structures use external reset signal and control to make sure the MCU be reset under power dropping and under dead-band. The external reset information is described in the next section.



3.5 EXTERNAL RESET

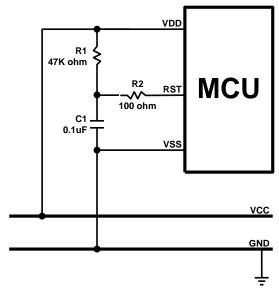
External reset function is controlled by "Reset_Pin" code option. Set the code option as "Reset" option to enable external reset function. External reset pin is Schmitt Trigger structure and low level active. The system is running when reset pin is high level voltage input. The reset pin receives the low voltage and the system is reset. The external reset operation actives in power on and normal running mode. During system power-up, the external reset pin must be high level input, or the system keeps in reset status. External reset sequence is as following.

- External reset (only external reset pin enable): System checks external reset pin status. If external reset pin is not high level, the system keeps reset status and waits external reset pin released.
- System initialization: All system registers is set as initial conditions and system is ready.
- Oscillator warm up: Oscillator operation is successfully and supply to system clock.
- Program executing: Power on sequence is finished and program executes from ORG 0.

The external reset can reset the system during power on duration, and good external reset circuit can protect the system to avoid working at unusual power condition, e.g. brown out reset in AC power application...

3.6 EXTERNAL RESET CIRCUIT

3.6.1 Simply RC Reset Circuit

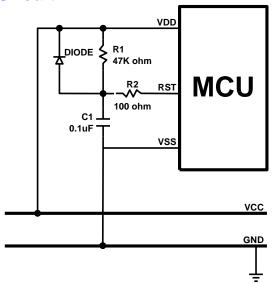


This is the basic reset circuit, and only includes R1 and C1. The RC circuit operation makes a slow rising signal into reset pin as power up. The reset signal is slower than VDD power up timing, and system occurs a power on signal from the timing difference.

Note: The reset circuit is no any protection against unusual power or brown out reset.



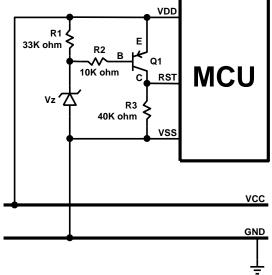
3.6.2 Diode & RC Reset Circuit



This is the better reset circuit. The R1 and C1 circuit operation is like the simply reset circuit to make a power on signal. The reset circuit has a simply protection against unusual power. The diode offers a power positive path to conduct higher power to VDD. It is can make reset pin voltage level to synchronize with VDD voltage. The structure can improve slight brown out reset condition.

Note: The R2 100 ohm resistor of "Simply reset circuit" and "Diode & RC reset circuit" is necessary to limit any current flowing into reset pin from external capacitor C in the event of reset pin breakdown due to Electrostatic Discharge (ESD) or Electrical Over-stress (EOS).

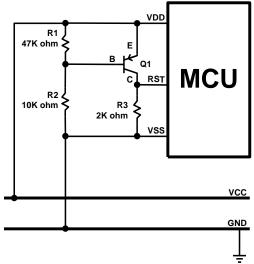
3.6.3 Zener Diode Reset Circuit



The zener diode reset circuit is a simple low voltage detector and can **improve brown out reset condition completely**. Use zener voltage to be the active level. When VDD voltage level is above "Vz + 0.7V", the C terminal of the PNP transistor outputs high voltage and MCU operates normally. When VDD is below "Vz + 0.7V", the C terminal of the PNP transistor outputs low voltage and MCU is in reset mode. Decide the reset detect voltage by zener specification. Select the right zener voltage to conform the application.



3.6.4 Voltage Bias Reset Circuit

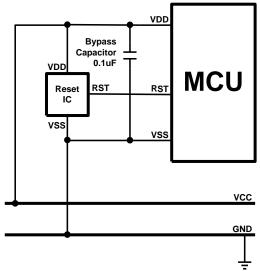


The voltage bias reset circuit is a low cost voltage detector and can **improve brown out reset condition completely**. The operating voltage is not accurate as zener diode reset circuit. Use R1, R2 bias voltage to be the active level. When VDD voltage level is above or equal to "0.7V x (R1 + R2) / R1", the C terminal of the PNP transistor outputs high voltage and MCU operates normally. When VDD is below "0.7V x (R1 + R2) / R1", the C terminal of the PNP transistor outputs low voltage and MCU is in reset mode.

Decide the reset detect voltage by R1, R2 resistances. Select the right R1, R2 value to conform the application. In the circuit diagram condition, the MCU's reset pin level varies with VDD voltage variation, and the differential voltage is 0.7V. If the VDD drops and the voltage lower than reset pin detect level, the system would be reset. If want to make the reset active earlier, set the R2 > R1 and the cap between VDD and C terminal voltage is larger than 0.7V. The external reset circuit is with a stable current through R1 and R2. For power consumption issue application, e.g. DC power system, the current must be considered to whole system power consumption.

Note: Under unstable power condition as brown out reset, "Zener diode rest circuit" and "Voltage bias reset circuit" can protects system no any error occurrence as power dropping. When power drops below the reset detect voltage, the system reset would be triggered, and then system executes reset sequence. That makes sure the system work well under unstable power situation.

3.6.5 External Reset IC



The external reset circuit also use external reset IC to enhance MCU reset performance. This is a high cost and good effect solution. By different application and system requirement to select suitable reset IC. The reset circuit can improve all power variation.





SYSTEM CLOCK

4.1 OVERVIEW

The micro-controller is a dual clock system including high-speed and low-speed clocks. The high-speed clock includes internal high-speed oscillator and external oscillators selected by "High_CLK" code option. The low-speed clock is from internal low-speed oscillator controlled by "CLKMD" bit of OSCM register. Both high-speed clock and low-speed clock can be system clock source through a divider to decide the system clock rate.

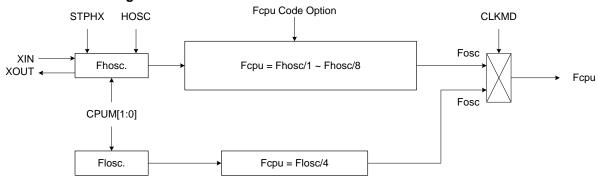
High-speed oscillator

Internal high-speed oscillator is 8MHz RC type called "**IHRC**". External high-speed oscillator includes crystal/ceramic (4MHz, 8MHz, 455KHz) and RC type.

Low-speed oscillator

Internal low-speed oscillator is 10KHz @3V RC type called "ILRC".

System clock block diagram



- HOSC: High_Clk code option.
- Fhosc: External high-speed clock / Internal high-speed RC clock.
- Flosc: Internal low-speed RC clock (about 10KHz@3V).
- Fosc: System clock source.
- Fcpu: Instruction cycle.

4.2 FCPU (INSTRUCTION CYCLE)

The system clock rate is instruction cycle called "**Fcpu**" which is divided from the system clock source and decides the system operating rate. Fcpu rate is selected by Fcpu code option and the range is Fhosc/1~Fhosc/8 under system normal mode. If the system high clock source is external 4MHz crystal, and the Fcpu code option is Fhosc/4, the Fcpu frequency is 4MHz/4 = 1MHz. Under system slow mode, the Fcpu is fixed Flosc/4, 10KHz/4=2.5KHz @3V.

In high noisy environment, below "Fhosc/4" of Fcpu code option is the strongly recommendation to reduce high frequency noise effect.



4.3 SYSTEM HIGH-SPEED CLOCK

The system high-speed clock has internal and external two-type. The external high-speed clock includes 4MHz, 8MHz, 455KHz crystal/ceramic and RC type. These high-speed oscillators are selected by "**High_CLK**" code option.

4.3.1 HIGH_CLK CODE OPTION

For difference clock functions, Sonix provides multi-type system high clock options controlled by "High_CLK" code option. The High_CLK code option defines the system oscillator types including IHRC_8M, RC, 455K X'tal, 8M X'tal and 4M X'tal. These oscillator options support different bandwidth oscillator.

- **HRC_8M:** The system high-speed clock source is internal high-speed 8MHz RC type oscillator. In the mode, XIN and XOUT pins are bi-direction GPIO mode, and not to connect any external oscillator device.
- * RC: The system high-speed clock source is external low cost RC type oscillator. The RC oscillator circuit only connects to XIN pin, and the XOUT pin is bi-direction GPIO mode.
- **455K X'tal:** The system high-speed clock source is external low-speed crystal. The option support 32KHz and 455KHz crystals.
- * 8M X'tal: The system high-speed clock source is external high-speed crystal/ceramic. The oscillator bandwidth is 4MHz~8MHz.
- **4M X'tal:** The system high-speed clock source is external high-speed crystal/resonator. The oscillator bandwidth is 1MHz~4MHz.

4.3.2 INTERNAL HIGH-SPEED OSCILLATOR RC TYPE (IHRC)

The internal high-speed oscillator is 8MHz RC type. The accuracy is $\pm 2\%$ under commercial condition. When the "High_CLK" code option is "IHRC_8M", the internal high-speed oscillator is enabled.

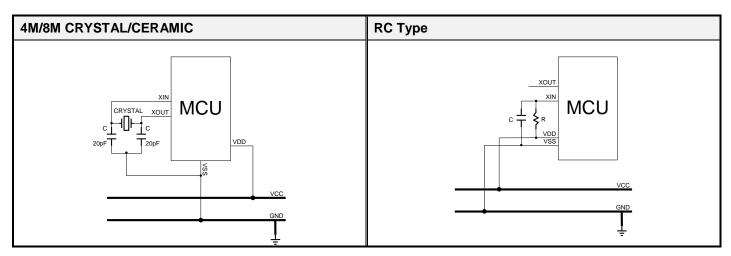
• IHRC_8M: The system high-speed clock is internal 8MHz oscillator RC type. XIN/XOUT pins are general purpose I/O pins.

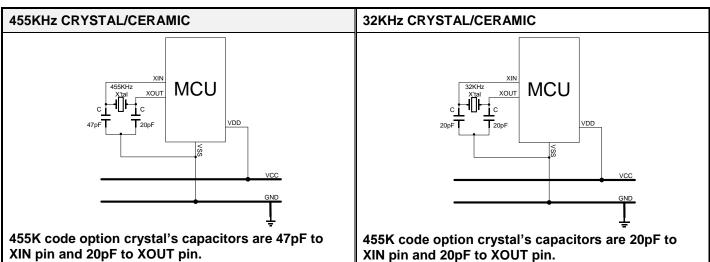
4.3.3 EXTERNAL HIGH-SPEED OSCILLATOR

The external high-speed oscillator includes 4MHz, 8MHz, 455KHz and RC type. The 4MHz, 8MHz and 455KHz oscillators support crystal and ceramic types connected to XIN/XOUT pins with 20pF capacitors to ground. The RC type is a low cost RC circuit only connected to XIN pin. The capacitance is not below 100pF, and use the resistance to decide the frequency.



4.3.4 EXTERNAL OSCILLATOR APPLICATION CIRCUIT



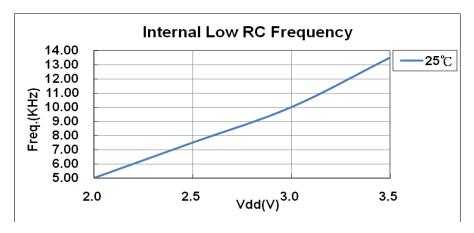


Note: Connect the Crystal/Ceramic and C as near as possible to the XIN/XOUT/VSS pins of micro-controller. Connect the R and C as near as possible to the VDD pin of micro-controller.



4.4 SYSTEM LOW-SPEED CLOCK

The system low clock source is the internal low-speed oscillator built in the micro-controller. The low-speed oscillator uses RC type oscillator circuit. The frequency is affected by the voltage and temperature of the system. In common condition, the frequency of the RC oscillator is about 10KHz at 3V. The relation between the RC frequency and voltage is as the following figure.



The internal low RC supports watchdog clock source and system slow mode controlled by "CLKMD" bit of OSCM register.

- Flosc = Internal low RC oscillator (about 10KHz @3V).
- Slow mode Fcpu = Flosc / 4

There are two conditions to stop internal low RC. One is power down mode, and the other is green mode of 455K mode and watchdog disable. If system is in 455K mode and watchdog disable, only 455K oscillator actives and system is under low power consumption.

> Example: Stop internal low-speed oscillator by power down mode.

B0BSET FCPUM0 ; To stop external high-speed oscillator and internal low-speed

; oscillator called power down mode (sleep mode).

Note: The internal low-speed clock can't be turned off individually. It is controlled by CPUM0, CPUM1 (455K, watchdog disable) bits of OSCM register.



4.5 OSCM REGISTER

The OSCM register is an oscillator control register. It controls oscillator status, system mode.

0CAH	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
OSCM	0	0	0	CPUM1	CPUM0	CLKMD	STPHX	0
Read/Write	-	-	-	R/W	R/W	R/W	R/W	-
After reset	-	-	-	0	0	0	0	-

Bit 1 STPHX: External high-speed oscillator control bit.

0 = External high-speed oscillator free run.

1 = External high-speed oscillator free run stop. Internal low-speed RC oscillator is still running.

Bit 2 **CLKMD:** System high/Low clock mode control bit.

0 = Normal (dual) mode. System clock is high clock.

1 = Slow mode. System clock is internal low clock.

Bit[4:3] CPUM[1:0]: CPU operating mode control bits.

00 = normal.

01 = sleep (power down) mode.

10 = green mode.

11 = reserved.

"STPHX" bit controls internal high speed RC type oscillator and external oscillator operations. When "STPHX=0", the external oscillator or internal high speed RC type oscillator active. When "STPHX=1", the external oscillator or internal high speed RC type oscillator are disabled. The STPHX function is depend on different high clock options to do different controls.

- IHRC 8M: "STPHX=1" disables internal high speed RC type oscillator.
- RC, 4M, 8M, 455K: "STPHX=1" disables external oscillator.

4.6 SYSTEM CLOCK MEASUREMENT

Under design period, the users can measure system clock speed by software instruction cycle (Fcpu). This way is useful in RC mode.

> Example: Fcpu instruction cycle of external oscillator.

B0BSET P0M.0 ; Set P0.0 to be output mode for outputting Fcpu toggle signal.

@@:

B0BSET P0.0 ; Output Fcpu toggle signal in low-speed clock mode. B0BCLR P0.0 ; Measure the Fcpu frequency by oscilloscope.

JMP @B

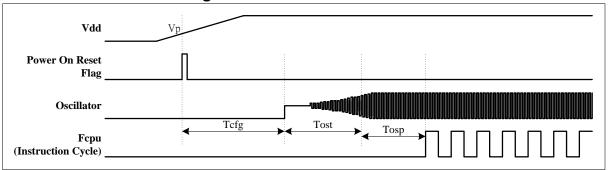
Note: Do not measure the RC frequency directly from XIN; the probe impendence will affect the RC frequency.



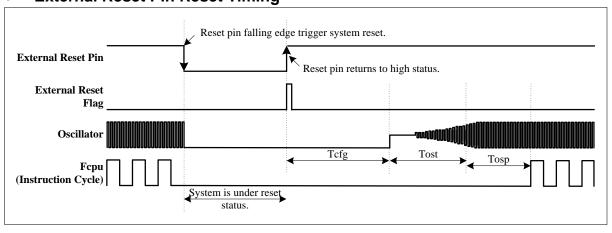
4.7 SYSTEM CLOCK TIMING

Parameter	Symbol	Description	Typical
Hardware configuration time	Tcfg	2048*F _{ILRC}	64ms @ F _{ILRC} = 32KHz 128ms @ F _{ILRC} = 16KHz
Oscillator start up time	Tost	The start-up time is depended on oscillator's material, factory and architecture. Normally, the low-speed oscillator's start-up time is lower than high-speed oscillator. The RC type oscillator's start-up time is faster than crystal type oscillator.	-
Oscillator warm-up time	Tosp	Oscillator warm-up time of reset condition. 2048*F _{hosc} (Power on reset, LVD reset, watchdog reset, external reset pin active.)	64ms @ F _{hosc} = 32KHz 512us @ F _{hosc} = 4MHz 256us @ F _{hosc} = 8MHz
		Oscillator warm-up time of power down mode wake-up condition. 2048*F _{hosc} Crystal/resonator type oscillator, e.g. 32768Hz crystal, 4MHz crystal, 16MHz crystal 32*F _{hosc} RC type oscillator, e.g. external RC type oscillator, internal high-speed RC type oscillator.	64ms @ F _{hosc} = 32KHz 512us @ F _{hosc} = 4MHz 256us @ F _{hosc} = 8MHz

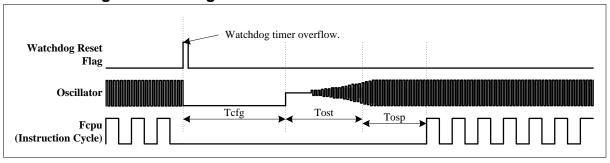
Power On Reset Timing



External Reset Pin Reset Timing

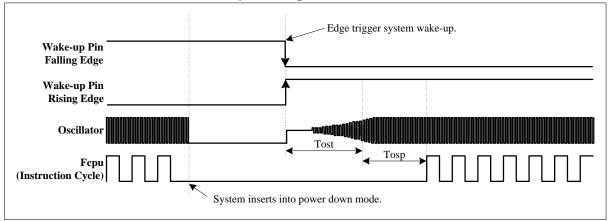


Watchdog Reset Timing

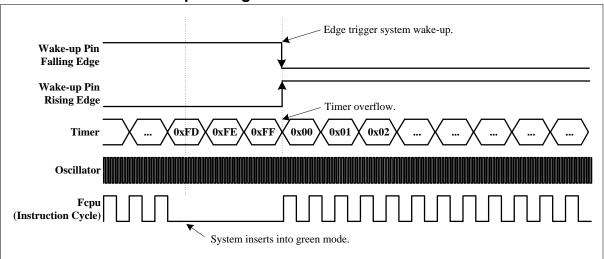




Power Down Mode Wake-up Timing

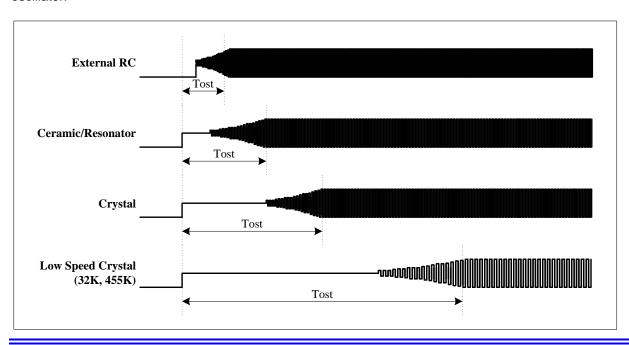


Green Mode Wake-up Timing



Oscillator Start-up Time

The start-up time is depended on oscillator's material, factory and architecture. Normally, the low-speed oscillator's start-up time is lower than high-speed oscillator. The RC type oscillator's start-up time is faster than crystal type oscillator.



Version 0.6



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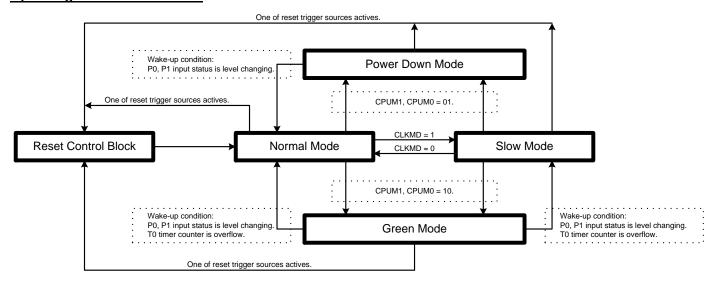
SYSTEM OPERATION MODE

5.1 OVERVIEW

The chip builds in four operating mode for difference clock rate and power saving reason. These modes control oscillators, op-code operation and analog peripheral devices' operation.

- Normal mode: System high-speed operating mode.
- Slow mode: System low-speed operating mode.
- Power down mode: System power saving mode (Sleep mode).
- Green mode: System ideal mode.

Operating Mode Control Block



Operating Mode Clock Control Table

Operating Mode	Normal Mode	Slow Mode	Green Mode	Power Down Mode
EHOSC	Running	By STPHX	By STPHX	Stop
IHRC	Running	By STPHX	By STPHX	Stop
ILRC	Running	Running	Running	Stop
CPU instruction	Executing	Executing	Stop	Stop
T0 timer	By T0ENB	By T0ENB	By T0ENB	Inactive
Watchdog timer	By Watch_Dog	By Watch_Dog	By Watch_Dog	By Watch_Dog
ŭ .	Code option	Code option	Code option	Code option
Internal interrupt	All active	All active	T0	All inactive
External interrupt	All active	All active	All active	All inactive
Wakeup source	-	-	P0, P1, T0, Reset	P0, P1, Reset

- **EHOSC:** External high-speed oscillator (XIN/XOUT).
- IHRC: Internal high-speed oscillator RC type.
- ILRC: Internal low-speed oscillator RC type.



5.2 NORMAL MODE

The Normal Mode is system high clock operating mode. The system clock source is from high speed oscillator. The program is executed. After power on and any reset trigger released, the system inserts into normal mode to execute program. When the system is wake-up from power down mode, the system also inserts into normal mode. In normal mode, the high speed oscillator actives, and the power consumption is largest of all operating modes.

- The program is executed, and full functions are controllable.
- The system rate is high speed.
- The high speed oscillator and internal low speed RC type oscillator active.
- Normal mode can be switched to other operating modes through OSCM register.
- Power down mode is wake-up to normal mode.
- Slow mode is switched to normal mode.
- Green mode from normal mode is wake-up to normal mode.

5.3 SLOW MODE

The slow mode is system low clock operating mode. The system clock source is from internal low speed RC type oscillator. The slow mode is controlled by CLKMD bit of OSCM register. When CLKMD=0, the system is in normal mode. When CLKMD=1, the system inserts into slow mode. The high speed oscillator won't be disabled automatically after switching to slow mode, and must be disabled by SPTHX bit to reduce power consumption. In slow mode, the system rate is fixed Flosc/4 (Flosc is internal low speed RC type oscillator frequency).

- The program is executed, and full functions are controllable.
- The system rate is low speed (Flosc/4).
- The internal low speed RC type oscillator actives, and the high speed oscillator is controlled by STPHX=1. In slow mode, to stop high speed oscillator is strongly recommendation.
- Slow mode can be switched to other operating modes through OSCM register.
- Power down mode from slow mode is wake-up to normal mode.
- Normal mode is switched to slow mode.
- Green mode from slow mode is wake-up to slow mode.

5.4 POWER DOWN MDOE

The power down mode is the system ideal status. No program execution and oscillator operation. Whole chip is under low power consumption status under 1uA. The power down mode is waked up by P0, P1 hardware level change trigger. P1 wake-up function is controlled by P1W register. Any operating modes into power down mode, the system is waked up to normal mode. Inserting power down mode is controlled by CPUM0 bit of OSCM register. When CPUM0=1, the system inserts into power down mode. After system wake-up from power down mode, the CPUM0 bit is disabled (zero status) automatically.

- The program stops executing, and full functions are disabled.
- All oscillators including external high speed oscillator, internal high speed oscillator and internal low speed oscillator stop.
- The power consumption is under 1uA.
- The system inserts into normal mode after wake-up from power down mode.
- The power down mode wake-up source is P0 and P1 level change trigger.
- Note: If the system is in normal mode, to set STPHX=1 to disable the high clock oscillator. The system is under no system clock condition. This condition makes the system stay as power down mode, and can be wake-up by P0, P1 level change trigger.



5.5 GREEN MODE

The green mode is another system ideal status not like power down mode. In power down mode, all functions and hardware devices are disabled. But in green mode, the system clock source keeps running, so the power consumption of green mode is larger than power down mode. In green mode, the program isn't executed, but the timer with wake-up function actives as enabled, and the timer clock source is the non-stop system clock. The green mode has 2 wake-up sources. One is the P0, P1 level change trigger wake-up. The other one is internal timer with wake-up function occurring overflow. That's mean users can setup one fix period to timer, and the system is waked up until the time out. Inserting green mode is controlled by CPUM1 bit of OSCM register. When CPUM1=1, the system inserts into green mode. After system wake-up from green mode, the CPUM1 bit is disabled (zero status) automatically.

- The program stops executing, and full functions are disabled.
- Only the timer with wake-up function actives.
- The oscillator to be the system clock source keeps running, and the other oscillators operation is depend on system operation mode configuration.
- If inserting green mode from normal mode, the system insets to normal mode after wake-up.
- If inserting green mode from slow mode, the system insets to slow mode after wake-up.
- The green mode wake-up sources are P0, P1 level change trigger and unique time overflow.
- PWN and buzzer output functions active in green mode, but the timer can't wake-up the system as overflow.
- * Note: Sonix provides "GreenMode" macro to control green mode operation. It is necessary to use "GreenMode" macro to control system inserting green mode.

 The macro includes three instructions. Please take care the macro length as using BRANCH type instructions, e.g. bts0, bts1, b0bts0, b0bts1, ins, incms, decs, decms, cmprs, jmp, or the routine would be error.



5.6 OPERATING MODE CONTROL MACRO

Sonix provides operating mode control macros to switch system operating mode easily.

Macro	Length	Description
SleepMode	1-word	The system insets into Sleep Mode (Power Down Mode).
GreenMode	3-word	The system inserts into Green Mode.
SlowMode	2-word	The system inserts into Slow Mode and stops high speed oscillator.
Slow2Normal	5-word	The system returns to Normal Mode from Slow Mode. The macro
		includes operating mode switch, enable high speed oscillator, high
		speed oscillator warm-up delay time.

> Example: Switch normal/slow mode to power down (sleep) mode.

SleepMode ; Declare "SleepMode" macro directly.

Example: Switch normal mode to slow mode.

SlowMode ; Declare "SlowMode" macro directly.

> Example: Switch slow mode to normal mode (The external high-speed oscillator stops).

Slow2Normal ; Declare "Slow2Normal" macro directly.

Example: Switch normal/slow mode to green mode.

GreenMode ; Declare "GreenMode" macro directly.

> Example: Switch normal/slow mode to green mode and enable T0 wake-up function.

; Set T0 timer wakeup function.

B0BCLR	FT0IEN	; To disable T0 interrupt service
B0BCLR	FT0ENB	; To disable T0 timer
MOV	A,#20H	•
B0MOV	T0M,A	; To set T0 clock = Fcpu / 64
MOV	A,#74H	·
B0MOV	T0C,A	; To set T0C initial value = 74H (To set T0 interval = 10 ms)
B0BCLR	FT0IEN	; To disable T0 interrupt service
B0BCLR	FT0IRQ	; To clear T0 interrupt request
B0BSET	FT0ENB	; To enable T0 timer

; Go into green mode

GreenMode ; Declare "GreenMode" macro directly.



5.7 WAKEUP

5.7.1 OVERVIEW

Under power down mode (sleep mode) or green mode, program doesn't execute. The wakeup trigger can wake the system up to normal mode or slow mode. The wakeup trigger sources are external trigger (P0 level change) and internal trigger (T0 timer overflow).

- Power down mode is waked up to normal mode. The wakeup trigger is only external trigger (P0 level change)
- Green mode is waked up to last mode (normal mode or slow mode). The wakeup triggers are external trigger (P0 level change) and internal trigger (T0 timer overflow).

5.7.2 WAKEUP TIME

When the system is in power down mode (sleep mode), the high clock oscillator stops. When waked up from power down mode, MCU waits for 2048 external high-speed oscillator clocks as the wakeup time to stable the oscillator circuit. After the wakeup time, the system goes into the normal mode.

Note: Wakeup from green mode is no wakeup time because the clock doesn't stop in green mode.

The value of the wakeup time is as the following.

The Wakeup time = 1/Fosc * 2048 (sec) + high clock start-up time

Note: The high clock start-up time is depended on the VDD and oscillator type of high clock.

Example: In power down mode (sleep mode), the system is waked up. After the wakeup time, the system goes into normal mode. The wakeup time is as the following.

The wakeup time = 1/Fosc * 2048 = 0.512 ms (Fosc = 4MHz) The total wakeup time = 0.512 ms + oscillator start-up time



5.7.3 P1W WAKEUP CONTROL REGISTER

Under power down mode (sleep mode) and green mode, the I/O ports with wakeup function are able to wake the system up to normal mode. The wake-up trigger edge is level changing. When wake-up pin occurs rising edge or falling edge, the system is waked up by the trigger edge. The Port 0 and Port 1 have wakeup function. Port 0 wakeup function always enables, but the Port 1 is controlled by the P1W register.

0C0H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
P1W	P17W	P16W	P15W	P14W	P13W	P12W	P11W	P10W
Read/Write	W	W	W	W	W	W	W	W
After reset	0	0	0	0	0	0	0	0

Bit[7:0] P10W~P17W: Port 1 wakeup function control bits.

0 = Disable P1n wakeup function.

1 = Enable P1n wakeup function.

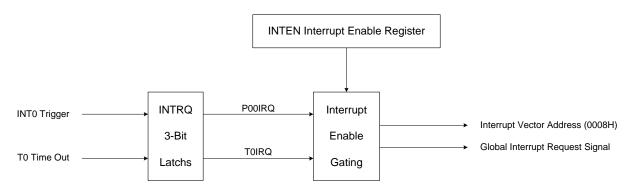


6

INTERRUPT

6.1 OVERVIEW

This MCU provides three interrupt sources, including one internal interrupt (T0) and one external interrupt (INT0). The external interrupt can wake-up the chip while the system is switched from power down mode to high-speed normal mode. Once interrupt service is executed, the GIE bit in STKP register will clear to "0" for stopping other interrupt request. On the contrast, when interrupt service exits, the GIE bit will set to "1" to accept the next interrupts' request. All of the interrupt request signals are stored in INTRQ register.



Note: The GIE bit must enable during all interrupt operation.

6.2 INTEN INTERRUPT ENABLE REGISTER

INTEN is the interrupt request control register including one internal interrupts, one external interrupts enable control bits. One of the register to be set "1" is to enable the interrupt request function. Once of the interrupt occur, the stack is incremented and program jump to ORG 8 to execute interrupt service routines. The program exits the interrupt service routine when the returning interrupt service routine instruction (RETI) is executed.

0C9H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
INTEN	-	-	-	TOIEN	-	-	-	P00IEN
Read/Write	-	-	-	R/W	-	-	-	R/W
After reset	-	-	-	0	-	-	-	0

Bit 0 **P00IEN:** External P0.0 interrupt (INT0) control bit.

0 = Disable INT0 interrupt function.1 = Enable INT0 interrupt function.

Bit 4 **TOIEN:** T0 timer interrupt control bit.

0 = Disable T0 interrupt function.1 = Enable T0 interrupt function.



6.3 INTRQ INTERRUPT REQUEST REGISTER

INTRQ is the interrupt request flag register. The register includes all interrupt request indication flags. Each one of the interrupt requests occurs, the bit of the INTRQ register would be set "1". The INTRQ value needs to be clear by programming after detecting the flag. In the interrupt vector of program, users know the any interrupt requests occurring by the register and do the routine corresponding of the interrupt request.

0C8H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
INTRQ	-	-	-	T0IRQ	-	-	-	P00IRQ
Read/Write	-	-	-	R/W	-	-	-	R/W
After reset	-	-	-	0	-	-	-	0

Bit 0 **P00IRQ:** External P0.0 interrupt (INT0) request flag.

0 = None INT0 interrupt request.

1 = INT0 interrupt request.

Bit 4 **T0IRQ:** T0 timer interrupt request flag.

0 = None T0 interrupt request.

1 = T0 interrupt request.

6.4 GIE GLOBAL INTERRUPT OPERATION

GIE is the global interrupt control bit. All interrupts start work after the GIE = 1 It is necessary for interrupt service request. One of the interrupt requests occurs, and the program counter (PC) points to the interrupt vector (ORG 8) and the stack add 1 level.

0DFH	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
STKP	GIE	-	-	-	-	-	STKPB1	STKPB0
Read/Write	R/W	-	-	-	-	-	R/W	R/W
After reset	0	-	-	-	-	-	1	1

Bit 7 GIE: Global interrupt control bit.

0 = Disable global interrupt.

1 = Enable global interrupt.

Example: Set global interrupt control bit (GIE).

B0BSET FGIE ; Enable GIE

Note: The GIE bit must enable during all interrupt operation.



6.5 PUSH, POP ROUTINE

When any interrupt occurs, system will jump to ORG 8 and execute interrupt service routine. It is necessary to save ACC, PFLAG data. The chip includes "PUSH", "POP" for in/out interrupt service routine. The two instructions save and load **ACC**, **PFLAG** data into buffers and avoid main routine error after interrupt service routine finishing.

- * Note: "PUSH", "POP" instructions save and load ACC/PFLAG without (NT0, NPD). PUSH/POP buffer is an unique buffer and only one level.
- Example: Store ACC and PAFLG data by PUSH, POP instructions when interrupt service routine executed.

ORG 0 JMP START

ORG 8

JMP INT_SERVICE

ORG 10H

START:

. . .

INT_SERVICE:

PUSH ; Save ACC and PFLAG to buffers.

- - -

POP ; Load ACC and PFLAG from buffers.

RETI ; Exit interrupt service vector

ENDP



6.6 EXTERNAL INTERRUPT OPERATION (INT0)

INTO is external interrupt trigger source and builds in edge trigger configuration function. When the external edge trigger occurs, the external interrupt request flag will be set to "1" no matter the external interrupt control bit enabled or disable. When external interrupt control bit is enabled and external interrupt edge trigger is occurring, the program counter will jump to the interrupt vector (ORG 8) and execute interrupt service routine.

The external interrupt builds in wake-up latch function. That means when the system is triggered wake-up from power down mode, the wake-up source is external interrupt source (P0.0), and the trigger edge direction matches interrupt edge configuration, the trigger edge will be latched, and the system executes interrupt service routine fist after wake-up.

0BFH	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
PEDGE	-	-	-	P00G1	P00G0	-	-	-
Read/Write	-	-	-	R/W	R/W	-	-	-
After reset	-	ı	-	1	0	-	ı	-

Bit[4:3] **P00G[1:0]:** INT0 edge trigger select bits.

00 = reserved,

01 = rising edge,

10 = falling edge,

11 = rising/falling bi-direction.

> Example: Setup INT0 interrupt request and bi-direction edge trigger.

MOV A, #18H

B0MOV PEDGE, A ; Set INT0 interrupt trigger as bi-direction edge.

BOBSET FP00IEN ; Enable INTO interrupt service BOBCLR FP00IRQ ; Clear INTO interrupt request flag

BOBSET FGIE ; Enable GIE

> Example: INT0 interrupt service routine.

INT_SERVICE:

ORG 8 ; Interrupt vector

JMP INT_SERVICE

... ; Push routine to save ACC and PFLAG to buffers.

B0BTS1 FP00IRQ ; Check P00IRQ

JMP EXIT_INT ; P00IRQ = 0, exit interrupt vector

B0BCLR FP00IRQ ; Reset P00IRQ

. ; INT0 interrupt service routine

; Pop routine to load ACC and PFLAG from buffers.

EXIT INT:

RETI ; Exit interrupt vector



6.7 TO INTERRUPT OPERATION

When the T0C counter occurs overflow, the T0IRQ will be set to "1" however the T0IEN is enable or disable. If the T0IEN = 1, the trigger event will make the T0IRQ to be "1" and the system enter interrupt vector. If the T0IEN = 0, the trigger event will make the T0IRQ to be "1" but the system will not enter interrupt vector. Users need to care for the operation under multi-interrupt situation.

Example: T0 interrupt request setup.

; Disable T0 interrupt service **B0BCLR FTOIEN** Disable T0 timer **B0BCLR** FT0ENB A, #20H MOV **B0MOV** TOM, A Set T0 clock = Fcpu / 64 MOV A. #74H Set T0C initial value = 74H **B0MOV** : Set T0 interval = 10 ms T0C, A **B0BSET FTOIEN** ; Enable T0 interrupt service **B0BCLR** FT0IRQ ; Clear T0 interrupt request flag **B0BSET** FT0ENB ; Enable T0 timer

B0BSET FGIE ; Enable GIE

> Example: T0 interrupt service routine.

ORG 8 ; Interrupt vector JMP INT_SERVICE

INT_SERVICE:

. ; Push routine to save ACC and PFLAG to buffers.

B0BTS1 FT0IRQ ; Check T0IRQ

JMP EXIT_INT ; T0IRQ = 0, exit interrupt vector

 B0BCLR
 FT0IRQ
 ; Reset T0IRQ

 MOV
 A, #74H

 B0MOV
 T0C, A
 ; Reset T0C.

... ; T0 interrupt service routine

EXIT INT:

... ; Pop routine to load ACC and PFLAG from buffers.

RETI ; Exit interrupt vector



6.8 MULTI-INTERRUPT OPERATION

Under certain condition, the software designer uses more than one interrupt requests. Processing multi-interrupt request requires setting the priority of the interrupt requests. The IRQ flags of interrupts are controlled by the interrupt event. Nevertheless, the IRQ flag "1" doesn't mean the system will execute the interrupt vector. In addition, which means the IRQ flags can be set "1" by the events without enable the interrupt. Once the event occurs, the IRQ will be logic "1". The IRQ and its trigger event relationship is as the below table.

Interrupt Name	Trigger Event Description				
P00IRQ	P0.0 trigger controlled by PEDGE				
T0IRQ	T0C overflow				

For multi-interrupt conditions, two things need to be taking care of. One is to set the priority for these interrupt requests. Two is using IEN and IRQ flags to decide which interrupt to be executed. Users have to check interrupt control bit and interrupt request flag in interrupt routine.

> Example: Check the interrupt request under multi-interrupt operation

ORG 8 ; Interrupt vector

JMP INT_SERVICE

INT_SERVICE:

... ; Push routine to save ACC and PFLAG to buffers.

INTP00CHK: ; Check INT0 interrupt request

B0BTS1 FP00IEN ; Check P00IEN

JMP INTTOCHK ; Jump check to next interrupt

B0BTS0 FP00IRQ ; Check P00IRQ JMP INTP00

INTT0CHK: ; Check T0 interrupt request

BOBTS1 FTOIEN ; Check TOIEN

JMP INT_EXIT ; End of interrupt request checking

JMP INT_EXIT ; End of interrupt request checking B0BTS0 FT0IRQ ; Check T0IRQ

JMP INTTO ; Jump to T0 interrupt service routine

... INT_EXIT:

... ; Pop routine to load ACC and PFLAG from buffers.

RETI ; Exit interrupt vector



7 I/O PORT

7.1 OVERVIEW

The micro-controller builds in 16 pin I/O. Some of the I/O pins are mixed with analog pins and special function pins. The I/O shared pin list is as following.

I/O F	Pin	Shared Pin		Shared Pin Control Condition
Name	Туре	Name	Туре	Shared Fill Control Condition
P0.0	I/O	INT0	DC	P00IEN=1
P0.2		, RST DC		Reset_Pin code option = Reset
PU.2	'	VPP	HV	OTP Programming
P0.4	I/O	XOUT	AC	High_CLK code option = 455K, 4M, 8M
P0.3	I/O	XIN	AC	High_CLK code option = RC, 455K, 4M, 8M
P5.4	I/O	IROUT	DC	IREN = 1.

^{*} DC: Digital Characteristic. AC: Analog Characteristic. HV: High Voltage Characteristic.



7.2 I/O PORT MODE

The port direction is programmed by PnM register. When the bit of PnM register is "0", the pin is input mode. When the bit of PnM register is "1", the pin is output mode.

0B8H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
P0M	P07M	P06M	P05M	P04M	P03M	-	P01M	P00M
Read/Write	R/W	R/W	R/W	R/W	R/W	-	R/W	R/W
After reset	0	0	0	0	0	-	0	0

0C1H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
P1M	P17M	P16M	P15M	P14M	P13M	P12M	P11M	P10M
Read/Write	R/W							
After reset	0	0	0	0	0	0	0	0

0C5H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
P5M	-	-	-	P54M	-	-	-	P50M
Read/Write	-	-	-	R/W	-	-	-	R/W
After reset	-	- 1	- 1	0	-	-	-	0

Bit[7:0] **PnM[7:0]:** Pn mode control bits. $(n = 0 \sim 5)$.

0 = Pn is input mode.

1 = Pn is output mode.

Note:

- 1. Users can program them by bit control instructions (B0BSET, B0BCLR).
- 2. P0.2 input only pin, and the P0M.2 is undefined.

> Example: I/O mode selecting

CLR POM ; Set all ports to be input mode.

CLR P1M CLR P5M

MOV A, #0FFH ; Set all ports to be output mode.

 B0MOV
 P0M, A

 B0MOV
 P1M,A

 B0MOV
 P5M, A

B0BCLR P1M.0 ; Set P1.0 to be input mode.

B0BSET P1M.0 ; Set P1.0 to be output mode.



7.3 I/O PULL UP REGISTER

The I/O pins build in internal pull-up resistors and only support I/O input mode. The port internal pull-up resistor is programmed by PnUR register. When the bit of PnUR register is "0", the I/O pin's pull-up is disabled. When the bit of PnUR register is "1", the I/O pin's pull-up is enabled.

0E0H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
P0UR	P07R	P06R	P05R	P04R	P03R	-	P01R	P00R
Read/Write	W	W	W	W	W	-	W	W
After reset	0	0	0	0	0	-	0	0

0E10H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
P1UR	P17R	P16R	P15R	P14R	P13R	P12R	P11R	P10R
Read/Write	W	W	W	W	W	W	W	W
After reset	0	0	0	0	0	0	0	0

0E5H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
P5UR	1	-	-	P54R	1	-	ı	P50R
Read/Write	1	-	-	W	1	-	ı	W
After reset	-	-	-	0	-	-	-	0

* Note: P0.2 is input only pin and without pull-up resister. The P0UR.2 is undefined.

> Example: I/O Pull up Register

MOV A, #0FFH ; Enable Port 0, 1, 5 Pull-up register,

BOMOV POUR, A BOMOV P1UR,A BOMOV P5UR, A



7.4 I/O PORT DATA REGISTER

0D0H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
P0	P07	P06	P05	P04	P03	P02	P01	P00
Read/Write	R/W	R/W	R/W	R/W	R/W	R	R/W	R/W
After reset	0	0	0	0	0	0	0	0

0D1H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
P1	P17	P16	P15	P14	P13	P12	P11	P10
Read/Write	R/W							
After reset	0	0	0	0	0	0	0	0

0D5H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
P5	-	-	-	P54	-	-	-	P50
Read/Write	-	ı	-	R/W	-	ı	ı	R/W
After reset	-		-	0	-	-	- 1	0

Note: The P02 keeps "1" when external reset enable by code option.

> Example: Read data from input port.

B0MOV A, P0 ; Read data from Port 0 B0MOV A, P1 ; Read data from Port 4 B0MOV A, P5 ; Read data from Port 5

> Example: Write data to output port.

MOV A, #0FFH ; Write data FFH to all Port.

B0MOV P0, A B0MOV P1, A B0MOV P5, A

> Example: Write one bit data to output port.

B0BSET P1.0 ; Set P1.0 and P5.3 to be "1". B0BSET P5.3

B0BCLR P1.0 ; Set P1.0 and P5.3 to be "0". B0BCLR P5.3



8 TIMERS

8.1 WATCHDOG TIMER

The watchdog timer (WDT) is a binary up counter designed for monitoring program execution. If the program goes into the unknown status by noise interference, WDT overflow signal raises and resets MCU. Watchdog clock controlled by code option and the clock source is internal low-speed oscillator (10KHz @3V).

Watchdog overflow time = 8192 / Internal Low-Speed oscillator (sec).

VDD	Internal Low RC Freq.	Watchdog Overflow Time
3V	10KHz	819.2ms

The watchdog timer has three operating options controlled "WatchDog" code option.

- **Disable:** Disable watchdog timer function.
- **Enable:** Enable watchdog timer function. Watchdog timer actives in normal mode and slow mode. In power down mode and green mode, the watchdog timer stops.
- Always_On: Enable watchdog timer function. The watchdog timer actives and not stop in power down mode and green mode.

In high noisy environment, the "Always_On" option of watchdog operations is the strongly recommendation to make the system reset under error situations and re-start again.

Watchdog clear is controlled by WDTR register. Moving 0x5A data into WDTR is to reset watchdog timer.

0CCH	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
WDTR	WDTR7	WDTR6	WDTR5	WDTR4	WDTR3	WDTR2	WDTR1	WDTR0
Read/Write	W	W	W	W	W	W	W	W
After reset	0	0	0	0	0	0	0	0

Example: An operation of watchdog timer is as following. To clear the watchdog timer counter in the top of the main routine of the program.

; Clear the watchdog timer.

Main:

MOV B0MOV	A, #5AH WDTR, A	
 CALL CALL	SUB1 SUB2	
 JMP	MAIN	

Example: Clear watchdog timer by "@RST_WDT" macro of Sonix IDE.

Main:

@RST_WDT		; Clear the watchdog timer.
CALL CALL	SUB1 SUB2	
 JMP	MAIN	



Watchdog timer application note is as following.

- Before clearing watchdog timer, check I/O status and check RAM contents can improve system error.
- Don't clear watchdog timer in interrupt vector and interrupt service routine. That can improve main routine fail.
- Clearing watchdog timer program is only at one part of the program. This way is the best structure to enhance the watchdog timer function.

Example: An operation of watchdog timer is as following. To clear the watchdog timer counter in the top of the main routine of the program.

Main:

... ; Check I/O. ... : Check RAM

Err: JMP \$; I/O or RAM error. Program jump here and don't

; clear watchdog. Wait watchdog timer overflow to reset IC.

Correct: ; I/O and RAM are correct. Clear watchdog timer and

; execute program.

V A, #5AH ; Clear the watchdog timer.

MOV A, #5AH
BOMOV WDTR, A
...
CALL SUB1
CALL SUB2
...
...
JMP MAIN

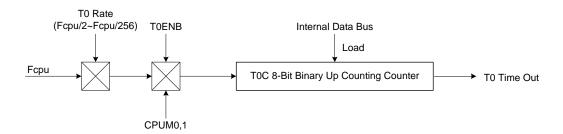


8.2 TIMER 0 (T0)

8.2.1 OVERVIEW

The T0 timer is an 8-bit binary up basic timer. If T0 timer occurs an overflow (from 0xFF to 0x00), it will continue counting and issue a time-out signal to indicate T0 time out event. The T0 builds in green mode wake-up function. When T0 timer overflow occurs under green mode, the system will be waked-up to last operating mode. The main purposes of the T0 timer are as following.

- **8-bit programmable up counting timer:** Generate time-out at specific time intervals based on the selected clock frequency.
- Interrupt function: To timer function supports interrupt function. When To timer occurs overflow, the TolRQ actives and the system points program counter to interrupt vector to do interrupt sequence.
- Green mode function: To keeps running in green mode and can wake-up from green mode as T0ENB = 1. System will be wake-up when T0IRQ actives after T0 timer overflow occurrence.



8.2.2 T0 Timer Operation

T0 timer is a basic 8-bit timer. T0 timer clock source is Fcpu. T0 unit time of Fcou clock source is decided by T0rate register including Fcpu/2, Fcpu/4, Fcpu/8, Fcpu/16, Fcpu/32, Fcpu/64, Fcpu/128 and Fcpu/256. When T0ENB=1, T0 timer starts to count. If the T0 counter is from 0xFF to 0x00, the T0 timer overflow occurs and T0IRQ sets as "1". If T0 interrupt function is enabled (T0IEN=1), the program counter is pointed to interrupt vector (ORG 8) to execute interrupt service routine after T0 timer overflow occurrence. T0 timer builds in green mode wake-up function. T0 timer keeps counting in green mode. When T0 timer overflow occurs, the system will be waked-up from green mode to last operating mode. T0 counter doesn't build in auto-reload function. Set the T0 interval time through setting T0C by program and have to set again when T0 timer overflows, or T0 timer counts from 0x00 to 0xFF 256 counts. Not keep the correct interval time.



8.2.3 TOM MODE REGISTER

0D8H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
TOM	T0ENB	T0rate2	T0rate1	T0rate0	-	-	-	-
Read/Write	R/W	R/W	R/W	R/W	-	-	-	-
After reset	0	0	0	0	-	-	-	-

Bit [6:4] TORATE[2:0]: TO internal clock select bits.

000 = fcpu/256.

001 = fcpu/128.

...

110 = fcpu/4.

111 = fcpu/2.

Bit 7 **T0ENB:** T0 counter control bit.

0 = Disable T0 timer.

1 = Enable T0 timer.

8.2.4 TOC COUNTING REGISTER

TOC is an 8-bit counter register for T0 interval time control.

0D9H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
T0C	T0C7	T0C6	T0C5	T0C4	T0C3	T0C2	T0C1	T0C0
Read/Write	R/W							
After reset	0	0	0	0	0	0	0	0

The equation of T0C initial value is as following.

T0C initial value = 256 - (T0 interrupt interval time * input clock)

Example: To set 10ms interval time for T0 interrupt. High clock is external 4MHz. Fcpu=Fosc/4. Select T0RATE=010 (Fcpu/64).

The basic timer table interval time of T0.

TORATE 7	T0CLOCK	High speed mode	(Fcpu = 4MHz / 4)	Low speed mode (Fcpu = 32768Hz / 4)		
	TUCLUCK	Max overflow interval	One step = max/256	Max overflow interval	One step = max/256	
000	Fcpu/256	65.536 ms	256 us	8000 ms	31250 us	
001	Fcpu/128	32.768 ms	128 us	4000 ms	15625 us	
010	Fcpu/64	16.384 ms	64 us	2000 ms	7812.5 us	
011	Fcpu/32	8.192 ms	32 us	1000 ms	3906.25 us	
100	Fcpu/16	4.096 ms	16 us	500 ms	1953.125 us	
101	Fcpu/8	2.048 ms	8 us	250 ms	976.563 us	
110	Fcpu/4	1.024 ms	4 us	125 ms	488.281 us	
111	Fcpu/2	0.512 ms	2 us	62.5 ms	244.141 us	



8.2.5 TO TIMER OPERATION SEQUENCE

T0 timer operation sequence of setup T0 timer is as following.

Stop T0 timer counting, disable T0 interrupt function and clear T0 interrupt request flag.

B0BCLR FT0ENB ; T0 timer.

B0BCLR FT0IEN ; T0 interrupt function is disabled. **B0BCLR** FT0IRQ ; T0 interrupt request flag is cleared.

Set T0 timer rate.

;The T0 rate control bits exist in bit4~bit6 of T0M. The MOV A, #0xxx0000b

; value is from x000xxxxb~x111xxxxb.

; T0 timer is disabled. **B0MOV** T0M,A

Set T0 interrupt interval time.

MOV A,#7FH

B0MOV T0C,A ; Set T0C value.

Set T0 timer function mode.

BOBSET ; Enable T0 interrupt function. FT0IEN

Enable T0 timer.

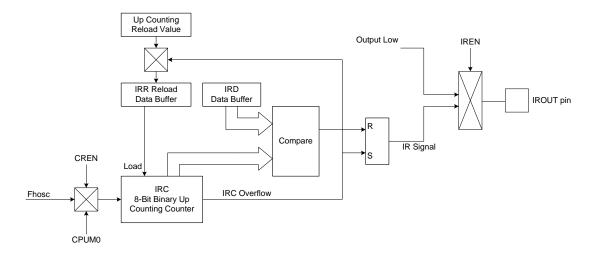
B0BSET FT0ENB ; Enable T0 timer.



9 IR OUTPUT

9.1 OVERVIEW

IR signal is generated by IR timer. The IR output pin is 400mA @Vss+0.5V sink type. When IREN bit of IRM is set as logic "1", IROUT pin exchanges from GPIO to IR output mode. If CREN = 0 or system is in power down mode, IROUT pin is tied to high status. The IR timer is an 8-bit binary up counting timer for IR signal generator. The IR signal is duty/cycle changeable type controlled by IRR and IRD. IRR decides IR's cycle and IRD decides IR's duty. IR counter clock source is only from Fhosc (system high clock source), eg. IHRC_8M, 4MHz or 455KHz crystal. If Fhosc is 4MHz, the IR counter clock rate is 4MHz. IR timer only generate IR output and no interrupt function. When enable IR output function (CREN=1), IR output status is low level. IRC initial value is IRR and starts to count. When IRC=IRD, IR output status change to high level and finishes low duty operation. When IRC overflow occurs (IRC changes from 0xFF to 0x00), IR output high duty operation stops. System loads IRR into IRC automatically and next cycle starts.



9.2 IR CONTROL REGISTER

9.2.1 IRM MODE REGISTER

0DAH	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
IRM	-	-	-	-	-	-	IREN	CREN
Read/Write	-	-	-	-	-	-	R/W	R/W
After reset	-	-	-	-	-	-	0	0

Bit 1 **IREN:** IROUT pin control bit.

0 = Disable. IROUT pin is P5.4 GPIO mode. 1 = Enable. IROUT pin is output high status.

Bit 0 **CREN:** IR carry signal output control bit.

0 = Disable. IROUT pin is output high status.

1 = Enable. IROUT pin outputs IR carry signal.

Note: IR carry output condition is IREN=1 and CREN=1. If CREN=1 and IREN=0, the IROUT pin is P5.4 GPIO mode.



9.2.2 IRC COUNTING REGISTER

IRC is an 8-bit counter register for IR interval time control.

0DBH	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
IRC	IRC7	IRC6	IRC5	IRC4	IRC3	IRC2	IRC1	IRC0
Read/Write	R/W							
After reset	0	0	0	0	0	0	0	0

Note: Set IRC=IRR before IR output enable to make sure the first cycle correct.

9.2.3 IRR AUTO-LOAD REGISTER

IRR decides IR signal frequency. IR timer is with auto-load function. When IRC overflow occurs, IRR value will load to IRC. It is easy to generate an accurate time for IR signal cycle, and users don't reset IRC during interrupt service routine.

IR is double buffer design. If new IRR value is set by program, the new value is stored in 1st buffer. Until IR overflow occurs, the new value moves to real IRR buffer.

0CDH	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
IRR	IRR7	IRR6	IRR5	IRR4	IRR3	IRR2	IRR1	IRR0
Read/Write	W	W	W	W	W	W	W	W
After reset	0	0	0	0	0	0	0	0

The equation of IRRinitial value is as following.

IRR initial value = 256 - (IR interrupt interval time * input clock)

Note: The input clock is 4MHz of external 4MHz oscillator.

Example: Set IR cycle frequency is 38KHz. Input clock is 4MHz.

IRR initial value = 256 - (IR interrupt interval time * input clock)

IR interval time = 1/38KHz = 26.3us Input clock = external oscillator 4MHz.

IRR = 256 - (26.3us * 4MHz) = 150.8

≈ 151

= 97h



9.2.4 IRD IR DUTY CONTROL REGISTER

The IR signal is duty changeable by IRD. IRD decides the IR output signal low pulse width length. When IRC=IRD, the IR signal changes from low pulse to high pulse. The low pulse stops when IRC overflow. The low pulse width is IRD-IRR, and the high pulse width is 256-IRD. It is easy to modulate IR duty/cycle by IRR and IRD registers.

0E8H	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
IRD	IRD7	IRD6	IRD5	IRD4	IRD3	IRD2	IRD1	IRD0
Read/Write	W	W	W	W	W	W	W	W
After reset	0	0	0	0	0	0	0	0

The equation of IRD initial value is as following.

Example: Set IRD for 38KHz IR and duty is 1/3. Input clock is 4MHz.

IRR of 38KHz = 151

$$IRD = 151 + (256-151)/(1/(1/3))$$

= 186
= **BAh**

Common IR signal table. System clock is 4MHz.

	IRO		IRD								
IR Freq. (KHz)	IRF	IRR 1/2 duty 1/3 duty		1/2 duty		ıty	1/4duty		1/4duty		Freq. Error Rate
(14.12)	DEC	HEX	DEC	HEX	DEC	HEX	DEC	HEX	rtuto		
32	131	83	193.50	C1	172.67	AC	162.25	A2	0.00%		
36	145	91	200.50	C8	182.00	В6	172.75	AC	0.10%		
38	151	97	203.50	СВ	186.00	ВА	177.25	B1	0.25%		
39.2	154	9A	205.00	CD	188.00	ВС	179.50	В3	0.04%		
40	156	9C	206.00	CE	189.33	BD	181.00	B5	0.00%		
56	185	В9	220.50	DC	208.67	D0	202.75	CA	0.60%		



9.3 IR OUTPUT OPERATION SEQUENCE

Set IRC and IRR for IR cycle.

MOV A, #IRCYCVAL ;IRC, IRR value for IR cycle.

MOV IRC, A MOV IRR, A

Set IRD for IR duty.

MOV A, #IRDUTYVAL ;IRD value for IR duty.

MOV IRD, A

Enable IR output.

BSET FIREN ; Set IROUT pin to IR carry output function.

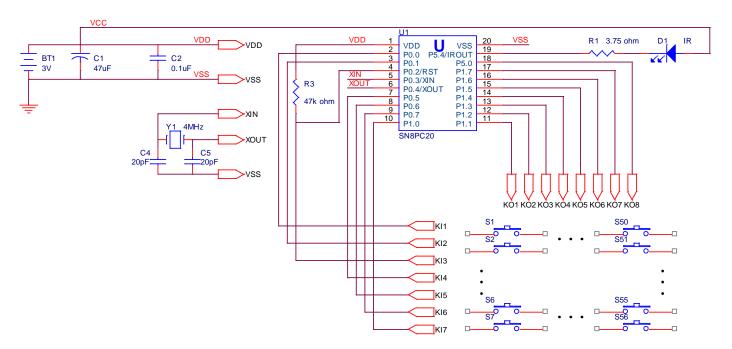
BSET FCREN ; Set IR carry signal output.



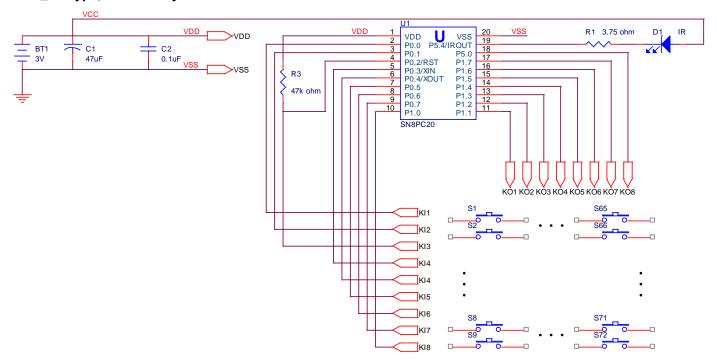
9.4 IR APPLICATION CIRCUIT

The IR sink current is 400mA @Vss+1.5V. The resistance of IR drive circuit is 3.75 ohm @Vdd=3V. The resistance can't lower than 3.75 ohm, or the sink current is over specification.

Crystal type, Max. 56 keys:



IHRC_8M type, Max. 72 keys:





10 INSTRUCTION TABLE

$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	- - - - - - - - - -	- - - - - -	\[- \] \[- \	1 1 1 1 1 1 1+N
O B0MOV A,M A \leftarrow M (bank 0) B0MOV M,A M (bank 0) \leftarrow A E MOV A,I A \leftarrow I B0MOV M,I M \leftarrow I, "M" only supports 0x80~0x87 registers (e.g. PFLAG,R,Y,Z)	- - - - - - - - - V	- - -	√ - - -	1 1 1
O	- - - - - - - -	- - -	-	1 1 1
V B0MOV M,A M (bank 0) \leftarrow A E MOV A,I A \leftarrow I B0MOV M,I M \leftarrow I, "M" only supports 0x80~0x87 registers (e.g. PFLAG,R,Y,Z)	- - - - - - - -	- - -	-	1
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	- - - - - V	-	-	1
B0MOV M,I M ← I, "M" only supports 0x80~0x87 registers (e.g. PFLAG,R,Y,Z)	- - - - V	-	-	=
	- \ \ \	- - -	-	1±NI
	- \ \ \	-		ITIN
BOXCH A,M A \longleftrightarrow M (bank 0)	\ \ \	-	-	1+N
MOVC $R, A \leftarrow ROM[Y,Z]$	V		-	2
ADC A,M A \leftarrow A + M + C, if occur carry, then C=1, else C=0	V	V	√	1
A ADC M,A M \leftarrow A + M + C, if occur carry, then C=1, else C=0		V	V	1+N
R ADD A,M A \leftarrow A + M, if occur carry, then C=1, else C=0	$\sqrt{}$	V	Ì	1
I ADD M,A M \leftarrow A + M, if occur carry, then C=1, else C=0	V	V	Ì	1+N
T B0ADD M,A M (bank 0) ← M (bank 0) + A, if occur carry, then C=1, else C=0	1	V	V	1+N
H ADD A,I A \leftarrow A + I, if occur carry, then C=1, else C=0	V	V	Ì	1
M SBC A,M A \leftarrow A - M - /C, if occur borrow, then C=0, else C=1	1	V	V	1
E SBC M,A M ← A - M - /C, if occur borrow, then C=0, else C=1	V	V	Ì	1+N
T SUB A,M A \leftarrow A - M, if occur borrow, then C=0, else C=1	V	V	Ì	1
SUB M,A M \leftarrow A - M, if occur borrow, then C=0, else C=1	1	V	Ì	1+N
C SUB A,I A ← A - I, if occur borrow, then C=0, else C=1	V	V	V	1
AND A,M A \leftarrow A and M		<u> </u>	\ √	1
L AND M,A M \leftarrow A and M		_	1	1+N
O AND A,I A \leftarrow A and I		-	1	1
			1	1
	-	-	1	1+N
I OR M,A M ← A or M C OR A,I A ← A or I	-	-	√ √	1+11
	-	-	√ √	1
	-	-	√ √	1+N
	-	-	√ √	1+11
	-	-	٧	
SWAP M A (b3~b0, b7~b4) ←M(b7~b4, b3~b0)	=	-	-	1
P SWAPM M M(b3~b0, b7~b4) ← M(b7~b4, b3~b0)	=	-	-	1+N
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	V	-	-	1
O RRCM M M←RRC M	√ 	-	-	1+N
C RLC M A←RLC M	V	-	-	1
E RLCM M M←RLC M	V	-	-	1+N
S CLR M M←0	-	-	-	1
S BCLR M.b M.b ← 0	-	-	-	1+N
BSET M.b M.b ← 1	-	-	-	1+N
B0BCLR M.b M(bank 0).b ← 0	-	-	-	1+N
B0BSET M.b M(bank 0).b ← 1	-	-	-	1+N
CMPRS A,I $ZF,C \leftarrow A - I$, If $A = I$, then skip next instruction	V	-		1 + S
B CMPRS A,M $ZF,C \leftarrow A - M$, If A = M, then skip next instruction	V	-		1 + S
R INCS M A \leftarrow M + 1, If A = 0, then skip next instruction	-	-	-	1+ S
A INCMS M $M \leftarrow M + 1$, If M = 0, then skip next instruction	-	-	-	1+N+S
N DECS M A \leftarrow M - 1, If A = 0, then skip next instruction	-	-	-	1+ S
C DECMS M $M \leftarrow M - 1$, If $M = 0$, then skip next instruction	-	-	-	1+N+S
H BTS0 M.b If M.b = 0, then skip next instruction	-	-	-	1 + S
BTS1 M.b If M.b = 1, then skip next instruction	-	-	-	1 + S
B0BTS0 M.b If M(bank 0).b = 0, then skip next instruction	-	-	-	1 + S
B0BTS1 M.b If M(bank 0).b = 1, then skip next instruction	-	-	-	1 + S
JMP d PC15/14 ← RomPages1/0, PC13~PC0 ← d	-	-	-	2
CALL d Stack \leftarrow PC15~PC0, PC15/14 \leftarrow RomPages1/0, PC13~PC0 \leftarrow d	-		-	2
M RET PC ← Stack	-	-	-	2
I RETI PC ← Stack, and to enable global interrupt	-	-	-	2
S PUSH To push ACC and PFLAG (except NT0, NPD bit) into buffers.	-	-	-	1
C POP To pop ACC and PFLAG (except NT0, NPD bit) from buffers.	V	V	V	1
NOP No operation				1

Note: 1. "M" is system register or RAM. If "M" is system registers then "N" = 0, otherwise "N" = 1.

2. If branch condition is true then "S = 1", otherwise "S = 0".



11 ELECTRICAL CHARACTERISTIC

11.1 ABSOLUTE MAXIMUM RATING

Supply voltage (Vdd)	0.3V ~ 6.0V
Input in voltage (Vin)	Vss – 0.2V ~ Vdd + 0.2V
Operating ambient temperature (Topr)	
SN8PC20P, SN8PC20S, SN8PC20X, SN8PC2016S, SN8P2014S	0°C ~ + 70°C
Storage ambient temperature (Tstor)	

11.2 ELECTRICAL CHARACTERISTIC

DC CHARACTERISTIC

(All of voltages refer to Vss, Vdd = 3.0V, fosc = 4MHz,fcpu=1MHZ,ambient temperature is 25°C unless otherwise note.)

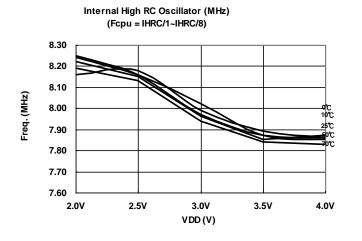
PARAMETER	SYM.	DESCI	RIPTION	MIN.	TYP.	MAX.	UNIT
Operating voltage	Vdd	Normal mode, Vpp = Vdo	d, 25°C, Fcpu = 2mips.	1.8	3.0	3.6	V
RAM Data Retention voltage	Vdr			1.5	-	-	V
Vdd rise rate	Vpor	Vdd rise rate to ensure in	ternal power-on reset	0.05	-	-	V/ms
Input Low Voltage	ViL1	All input ports		Vss	-	0.3Vdd	V
input Low voltage	ViL2	Reset pin		Vss	-	0.2Vdd	V
Input Lligh Voltage	ViH1	All input ports		0.7Vdd	-	Vdd	V
Input High Voltage	ViH2	Reset pin		0.9Vdd	-	Vdd	V
Reset pin leakage current	llekg	Vin = Vdd		-	-	2	uA
I/O port pull-up resistor	Rup	Vin = Vss , Vdd = 3V		100	200	300	ΚΩ
I/O port input leakage current	llekg	Pull-up resistor disable, \	/in = Vdd	-	-	2	uA
I/O output source current	loH	Vop = Vdd - 0.5V		8	10	-	A
•	loL1	Vop = Vss + 0.5V		8	12	-	mA
sink current	loL2	Vop = Vss + 1.5V, IR out	put pin	300	400	-	mA
INTn trigger pulse width	Tint0	INT0 interrupt request pu	llse width	2/fcpu	-	-	cycle
	ldd1	Run Mode (No loading, Fcpu = Fosc/4)	Vdd= 3V, 4Mhz	-	1	2	mA
Supply Current	ldd2	Slow Mode (Internal low RC, Stop high clock)	Vdd= 3V, 10Khz	1	5	10	uA
	ldd3	Sleep Mode	Vdd= 3V, 25°C	-	1	2	uA
		Green Mode	Vdd= 3V, 4Mhz	-	0.25	0.5	mA
	Idd4 (No loading, Fcpu = Fosc/4 Watchdog Disable)		Vdd=3V, ILRC 10Khz ,	-	3	6	uA
Internal High Oscillator Freq.	Fihrc	25 °C, Internal Hihg RC (IHRC) Vdd= 3V, Fcpu = 1MHz		7.84	8	8.16	Mhz
LVD Voltage	Vdet0	Low voltage reset level.		-	-	1.8	V

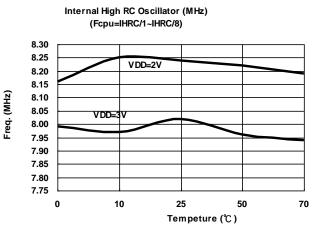
[&]quot; *" These parameters are for design reference, not tested.



11.3 CHARACTERISTIC GRAPHS

The graphs in this section are for design guidance, not tested or guaranteed. In some graphs, the data presented are outside specified operating range. This is for information only and devices are guaranteed to operate properly only within the specified range.







$12_{\sf DEVELOPMENT\ TOOL}$

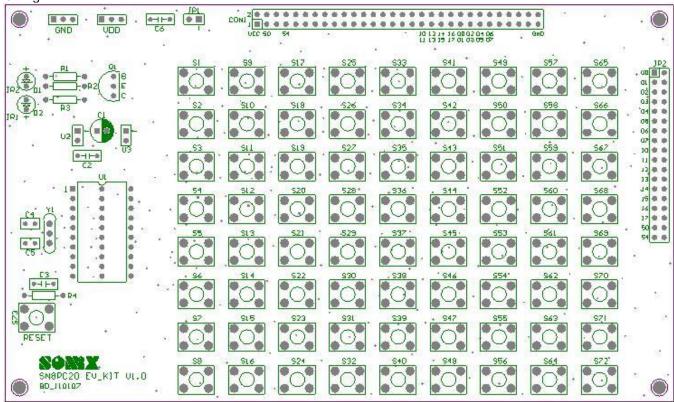
SONIX provides ICE (in circuit emulation), IDE (Integrated Development Environment) and EV-kit for SN8PC20 development. ICE and EV-kit are external hardware devices, and IDE is a friendly user interface for firmware development and emulation. These development tools' version is as following.

ICE: SN8ICE2K

EV-kit: SN8PC20 EV-kit V1.0.
IDE: SONIX IDE M2IDE_V115.
Writer: MPIII WRITER-LV.

12.1 SN8PC20 EV-KIT

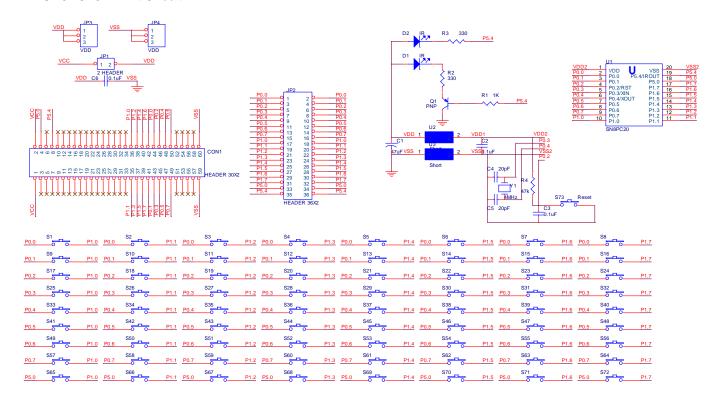
SN8PC20 EV-kit includes ICE interface, GPIO interface and IR driver module. The schematic of SN8PC20 EV-kit is as following.



- CON1: ICE interface connected to SN8ICE2K.
- JP1: EV-Kit power connector between VCC and VDD. VCC is the power source from SN8ICE2K. VDD is the power of KV-kit.
- JP2: GPIO connector for test.
- U1: SN8PC20 DIP and SSOP type connector for connecting to user's target board.
- U2/U3: Internal short connector. Don't care them as emulating.
- S1~S72: Remote key map.
- D1/R1/R2/Q1: IR driving circuit for ICE emulation.
- D2/R3: IR driving circuit for SN8PC20 real chip test. The two devices aren't set on SN8PC20 EV-kit.



SN8PC20 EV-kit Circuit



12.2 ICE AND EV-KIT APPLICATION NOTIC

SN8PC20 EV-kit includes matrix type key map and IR driving circuit module.

- The IR driving circuit module includes two types. One is for ICE emulation to drive IR carry signal. The other one is for SN8PC20 real chip test and disconnected with ICE. The EV-kit is like a real remote controller. The R3 resistance is over 3.75Ω better for 400mA sink current @Vdd=3V.
- If the SN8PC20 real chip is set as 455KHz oscillator mode, the C4 (XIN) capacitance must be 47pF and C5 (XOUT) capacitance must be 20pF.



13 OTP PROGRAMMING PIN

13.1 THE PIN ASSIGNMENT OF EASY WRITER TRANSITION BOARD SOCKET:

Easy Writer JP1/JP2									
VSS	2	1	VDD						
CE	4	3	CLK/PGCLK						
OE/ShiftDat	6	5	PGM/OTPCLK						
D0	8	7	D1						
D2	10	9	D3						
D4	12	11	D5						
D6	14	13	D7						
VPP	16	15	VDD						
RST	18	17	HLS						
ALSB/PDB	20	19	-						

JP1 for MP transition board

Easy Write	r JP3	(Map	ping to 48-pin text to
DIP1	1	48	DIP48
DIP2	2	47	DIP47
DIP3	3	46	DIP46
DIP4	4	45	DIP45
DIP5	5	44	DIP44
DIP6	6	43	DIP43
DIP7	7	42	DIP42
DIP8	8	41	DIP41
DIP9	9	40	DIP40
DIP10	10	39	DIP39
DIP11	11	38	DIP38
DIP12	12	37	DIP38
DIP13	13	36	DIP36
DIP14	14	35	DIP35
DIP15	15	34	DIP34
DIP16	16	33	DIP33
DIP17	17	32	DIP32
DIP18	18	31	DIP31
DIP19	19	30	DIP30
DIP20	20	29	DIP29
DIP21	21	28	DIP28
DIP22	22	27	DIP27
DIP23	23	26	DIP26
DIP24	24	25	DIP25

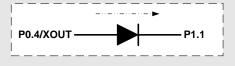
JP3 for MP transition board



13.2 PROGRAMMING PIN MAPPING:

		Progr	ammin	g Informa	tion of	SN8PC20		
Chip	Name	SN8PC20		SN8PC2		SN8PC20)14S	
	Writer inector			OTP IC	/ JP3 F	Pin Assignn	nent	
Number	Name	Number	Pin	Number	Pin	Number	Pin	
1	VDD	1	VDD	1	VDD	1	VDD	
2	GND	20	VSS	16	VSS	14	VSS	
3	CLK	12	P1.2	10	P1.2	10	P1.2	
4	CE	•	-	-	-	-	-	
5	PGM	10	P1.0	8	P1.0	8	P1.0	
6	OE	13	P1.3	11	P1.3	11	P1.3	
7	D1	•	-	-	-	ı	-	
8	D0	-	-	-	-	1	-	
9	D3	•	-	-	-	ı	-	
10	D2	•	-	-	-	ı	-	
11	D5	-	-	-	-	1	-	
12	D4	•	-	-	-	ı	-	
13	D7	•	-	-	-	ı	-	
14	D6	-	-	-	-	1	-	
15	VDD	-	-	-	-	1	-	
16	VPP	4	RST	4	RST	4	RST	
17	HLS		-	-	-	-	-	
18	RST	-	-	-	-	-	-	
19	-	•	-	-	-	-	-	
20	ALSB/PDB	6, 11	P0.4/ P1.1	6, 9	P0.4/ P1.1	6, 9	P0.4/ P1.1	

* Note: It is necessary to connect a diode between P0.4/XOUT (Pin 6) and P1.1 (Pin 11) of the writer's transition board. The direction of diode is P0.4/XOUT to P1.1 as below graphic.



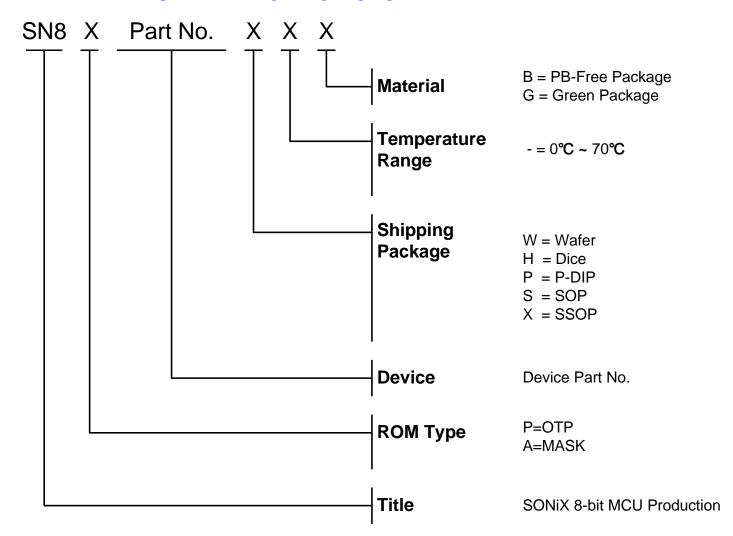


14 Marking Definition

14.1 INTRODUCTION

There are many different types in Sonix 8-bit MCU production line. This note listed the production definition of all 8-bit MCU for order or obtain information. This definition is only for Blank OTP MCU.

14.2 MARKING INDETIFICATION SYSTEM



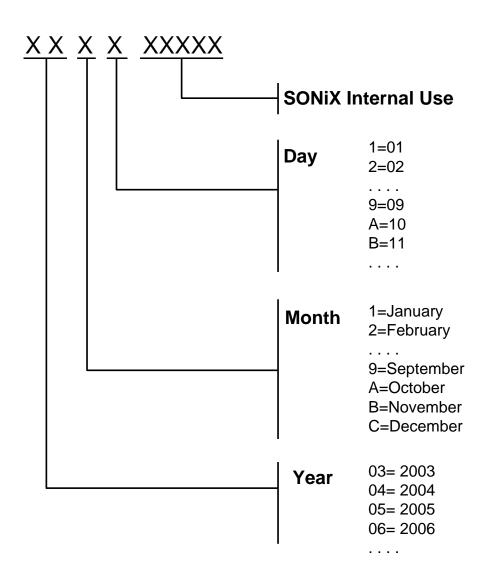
Note: SN8PC20 doesn't support -40°C~85°C temperature range.



14.3 MARKING EXAMPLE

Name	ROM Type	Device	Package	Temperature	Material
SN8PC20PG	OTP	C20	P-DIP	0°C~70°C	Green Package
SN8PC20SG	OTP	C20	SOP	0°C~70°C	Green Package
SN8PC20XG	OTP	C20	SSOP	0°C ~70°C	Green Package
SN8PC2016SG	OTP	C20	SOP	0°℃~70°℃	Green Package
SN8PC2014SG	OTP	C20	SOP	0°℃~70°℃	Green Package
SN8PC20W	OTP	C20	Wafer	0°C ~70°C	-
SN8PC20H	OTP	C20	Dice	0°C~70°C	-

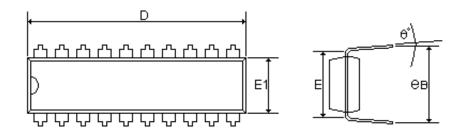
14.4 DATECODE SYSTEM

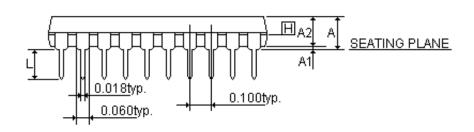




15 PACKAGE INFORMATION

15.1 P-DIP 20 PIN

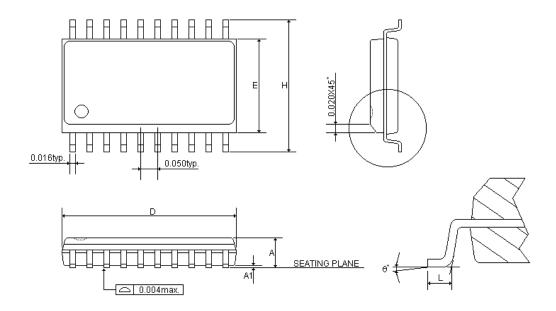




CVMDOLC	MIN	NOR	MAX	MIN	NOR	MAX		
SYMBOLS		(inch)		(mm)				
Α	-	-	0.210	-	-	5.334		
A1	0.015	-	-	0.381	-	-		
A2	0.125	0.130	0.135	3.175	3.302	3.429		
D	0.980	1.030	1.060	24.892	26.162	26.924		
Ε		0.300			7.620			
E1	0.245	0.250	0.255	6.223	6.350	6.477		
L	0.115	0.130	0.150	2.921	3.302	3.810		
eВ	0.335	0.355	0.375	8.509	9.017	9.525		
θ°	0°	7 °	15°	0°	7 °	15°		



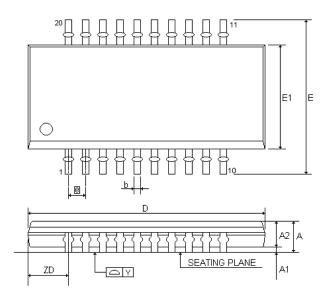
15.2 SOP 20 PIN

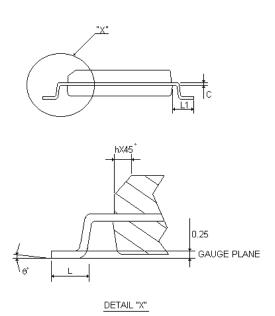


CVMDOLC	MIN	NOR	MAX	MIN	NOR	MAX		
SYMBOLS		(inch)		(mm)				
Α	0.093	0.099	0.104	2.362	2.502	2.642		
A1	0.004	0.008	0.012	0.102	0.203	0.305		
D	0.496	0.502	0.508	12.598	12.751	12.903		
E	0.291	0.295	0.299	7.391	7.493	7.595		
Н	0.394	0.407	0.419	10.008	10.325	10.643		
L	0.016	0.033	0.050	0.406	0.838	1.270		
θ°	0°	4 °	8°	<i>0</i> °	4 °	8°		



15.3 SSOP 20 PIN

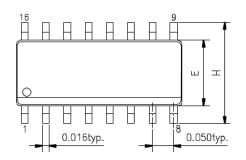


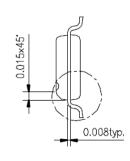


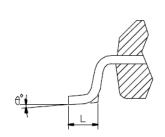
SYMBOLS	MIN	NOR	MAX	MIN	NOR	MAX	
STIMBULS		(inch)			(mm)		
Α	0.053	0.063	0.069	1.350	1.600	1.750	
A1	0.004	0.006	0.010	0.100	0.150	0.250	
A2	-	-	0.059	-	-	1.500	
b	0.008	0.010	0.012	0.200	0.254	0.300	
С	0.007	0.008	0.010	0.180	0.203	0.250	
D	0.337	0.341	0.344	8.560	8.660	8.740	
E	0.228	0.236	0.244	5.800	6.000	6.200	
E1	0.150	0.154	0.157	3.800	3.900	4.000	
[e]		0.025		0.635			
h	0.010	0.017	0.020	0.250	0.420	0.500	
L	0.016	0.025	0.050	0.400	0.635	1.270	
L1	0.039	0.041	0.043	1.000	1.050	1.100	
ZD		0.059			1.500		
Υ	-	-	0.004	-	-	0.100	
θ°	0 °	_	8°	O°	_	8°	

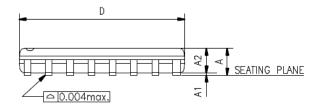


15.4 SOP 16 PIN









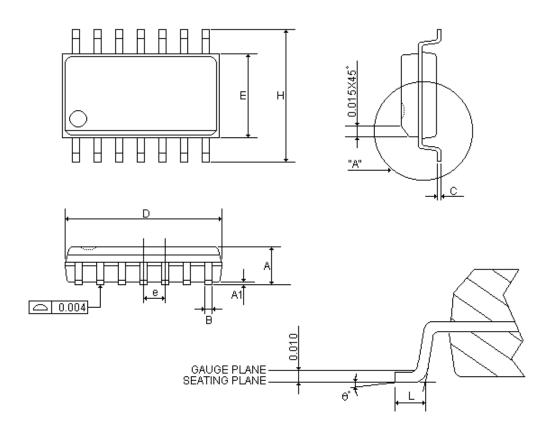
NOTES:

- 1.JEDEC OUTLINE : MS-012 AC.
- 2.DIMENSIONS "D" DOES NOT INCLUDE MOLD FLASH,
 PROTRUSIONS OR GATE BURRS.MOLD FLASH, PROTRUSIONS
 AND GATE BURRS SHALL NOT EXCEED .15mm (.006in)
 PER SIDE.
- 3.DIMENSIONS "E" DOES NOT INCLUDE INTER—LEAD FLASH, OR PROTRUSIONS. INTER—LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED .25mm (.010in) PER SIDE.

SYMBOLS	MIN	NOR	MAX	MIN	NOR	MAX
	(inch)			(mm)		
Α	0.053	-	0.069	1.346	-	1.753
A1	0.004	-	0.010	0.102	-	0.254
D	0.386	-	0.394	9.804	-	10.008
E	0.150	-	0.157	3.810	-	3.988
Н	0.228	-	0.244	5.791	-	6.198
L	0.016	-	0.050	0.406	-	1.270
θ°	0°	-	8°	0 °	-	8 °



15.5 SOP 14 PIN



SYMBOLS	MIN	NOR	MAX	MIN	NOR	MAX
	(inch)			(mm)		
Α	0.058	0.064	0.068	1.4732	1.6256	1.7272
A1	0.004	-	0.010	0.1016	-	0.254
В	0.013	0.016	0.020	0.3302	0.4064	0.508
С	0.0075	0.008	0.0098	0.1905	0.2032	0.2490
D	0.336	0.341	0.344	8.5344	8.6614	8.7376
Ε	0.150	0.154	0.157	3.81	3.9116	3.9878
е	-	0.050	-	-	1.27	-
Н	0.228	0.236	0.244	5.7912	5.9944	6.1976
L	0.015	0.025	0.050	0.381	0.635	1.27
θ°	0 °	-	8°	0 °	-	8°



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